

EUCAS2023

Bologna, Italy
3rd-7th September

Customizing coated conductors to enhance normal zone propagation velocities

Author: Pedro Barusco³

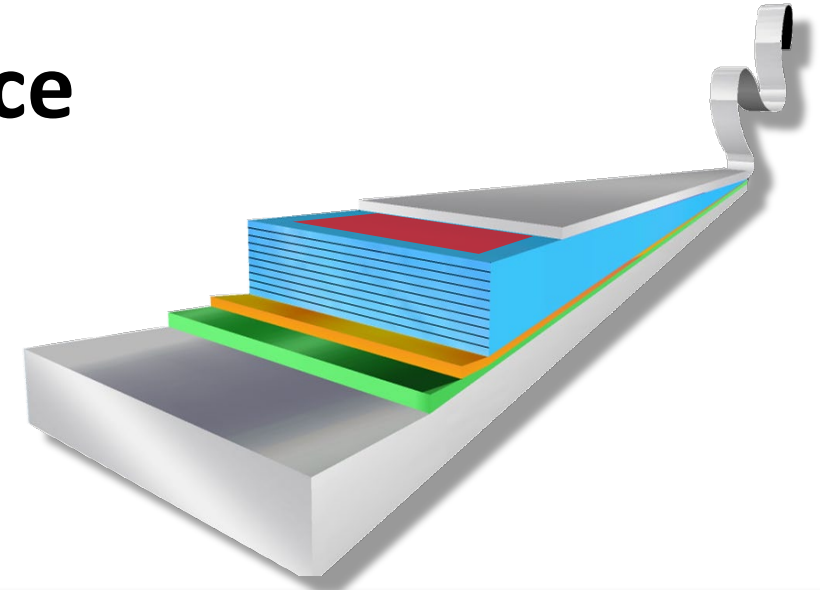
Presenter: Pedro Barusco³

Contributors : X. Obradors¹, X. Granados¹, T. Puig¹, C. Lacroix², F.Sirois²

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2 - Chemin de Polytechnique 2500, Montréal, Canada

3 - Renaissance Fusion, 22 Rue Jean Pierre Timbaud, 38600 Fontaine, France



□ Introduction

- HTS –tapes & Quench

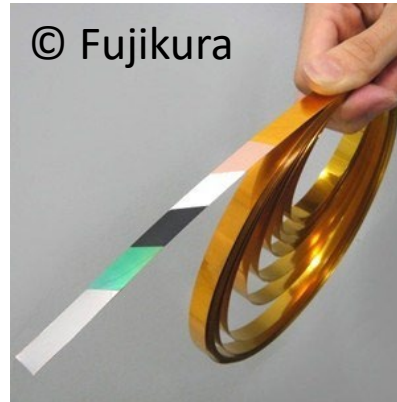
□ Motivation

- The hot-spot issue
- The Current Contact size
- The Current Flow Diverter (CFD)

□ Fabrication routes:

- 1st proposal: Local Annealing
- 2nd proposal: Yttria CFD
- 3rd proposal: IMC CFD
- 4rd proposal: Sulfide b-CFD

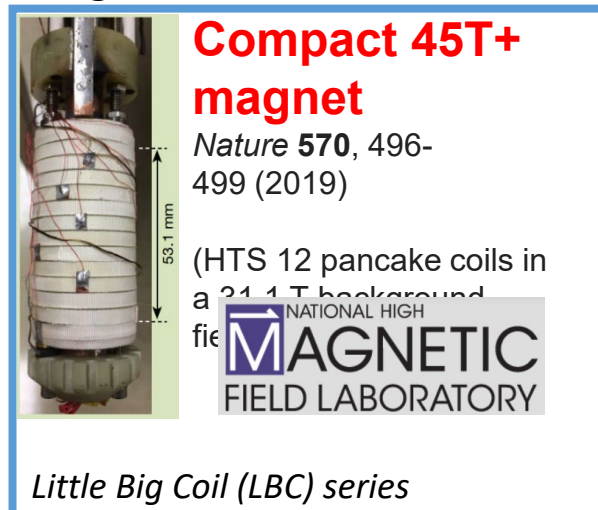
□ Conclusion & outlook



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High Temperature Superconducting (HTS) Tape

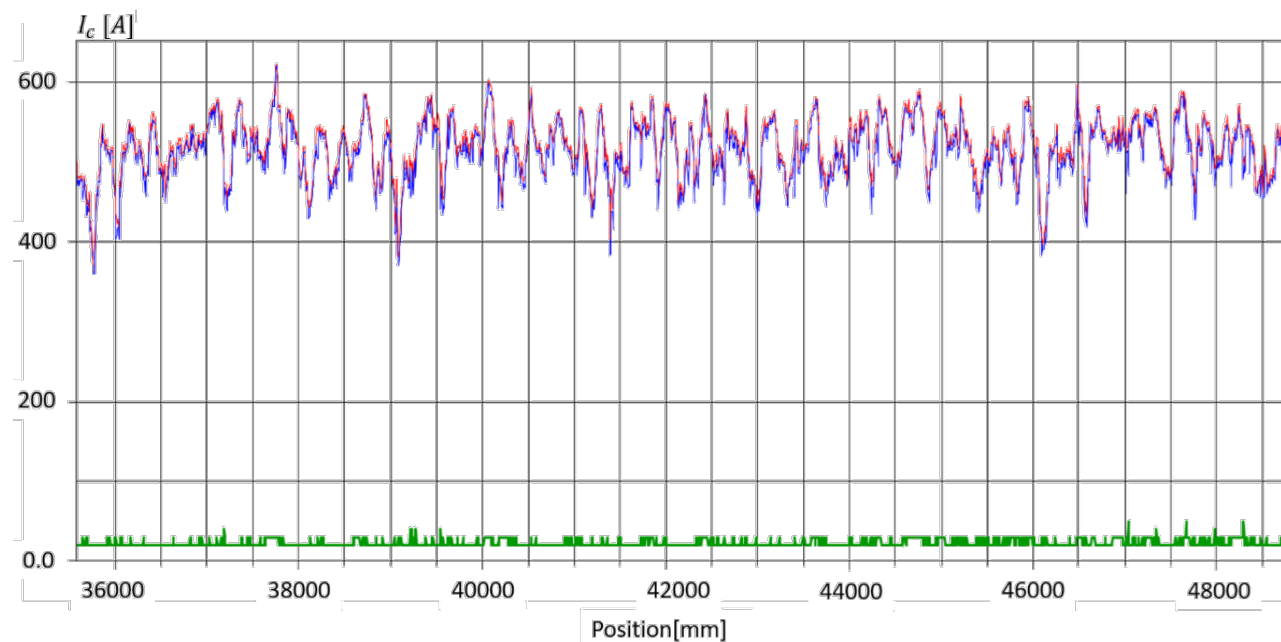
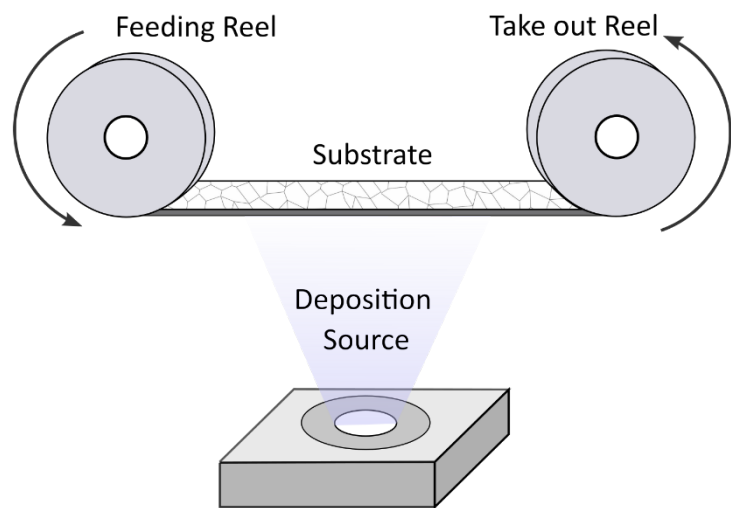
Superconducting High field magnets



Superconducting Fault current limiters (SFCL)



Motivation: The *hot-spot* regime



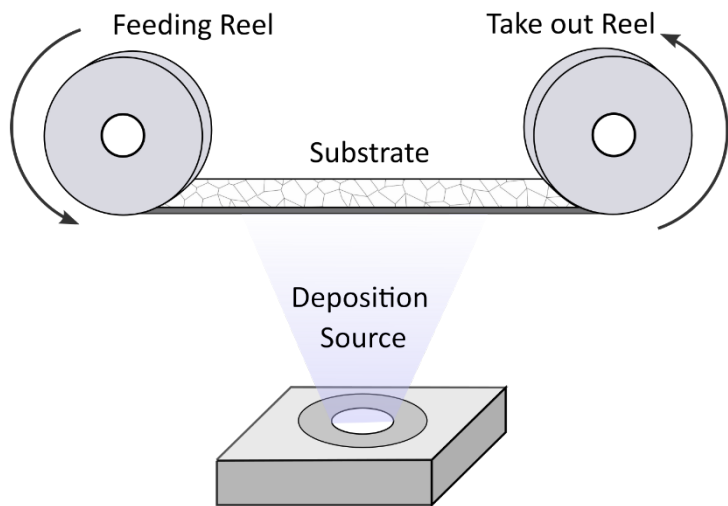
Video from Sebastian Hellmann – 3M-LS-O2.7 – EUCAS 2015



Superconductor 4mm, Superpower ReBCO-tape 40 μ m Cu-stabilization

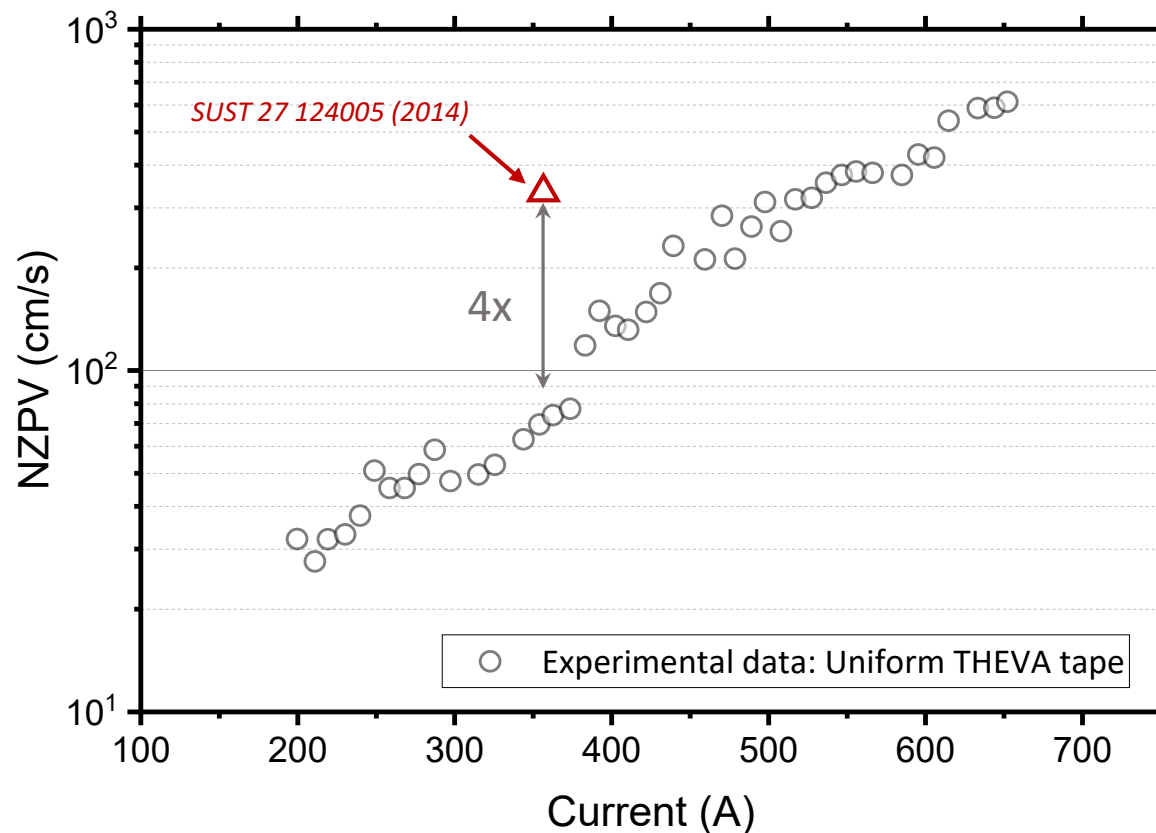


Motivation: The *hot-spot* regime

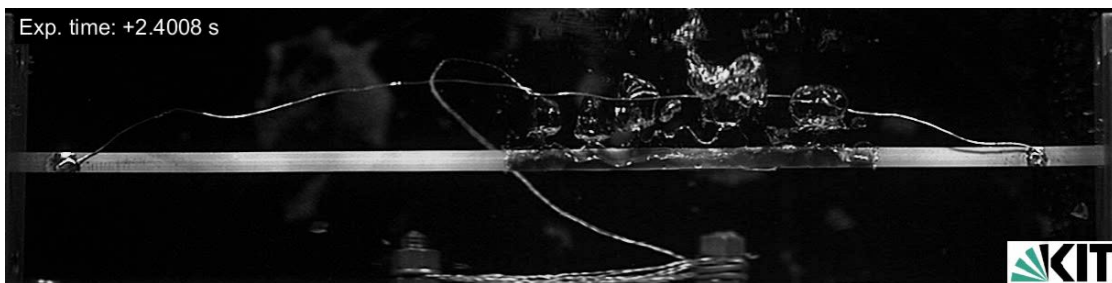


“... with an NZPV greater than 300 cm s^{-1} , it is possible to achieve a satisfying local thermal stability with relatively short HTS-CCs ...” (* at 365 A)

- Daniele Colangelo and Bertrand Dutoit *Supercond. Sci. Technol.* 27 124005 (2014)



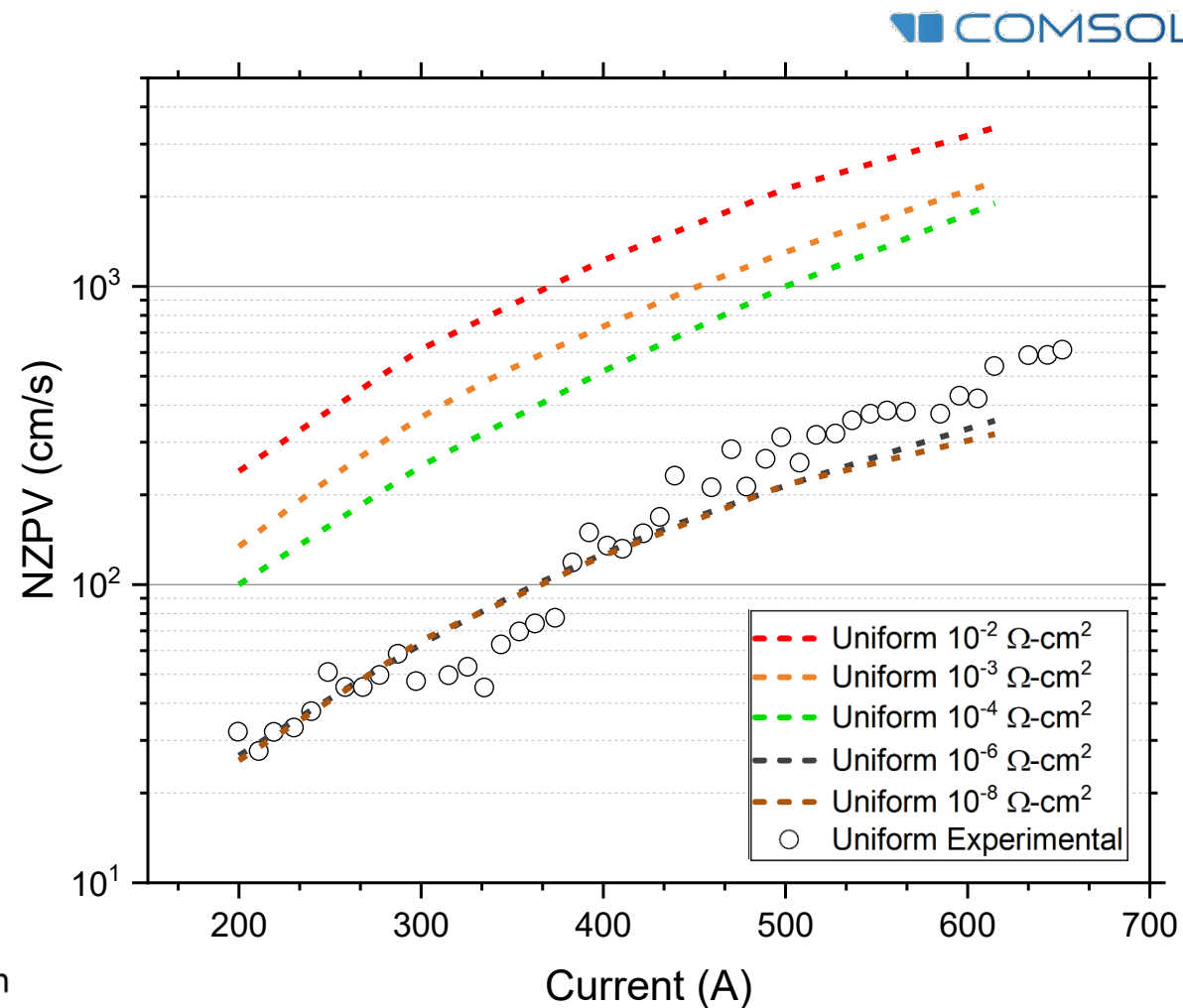
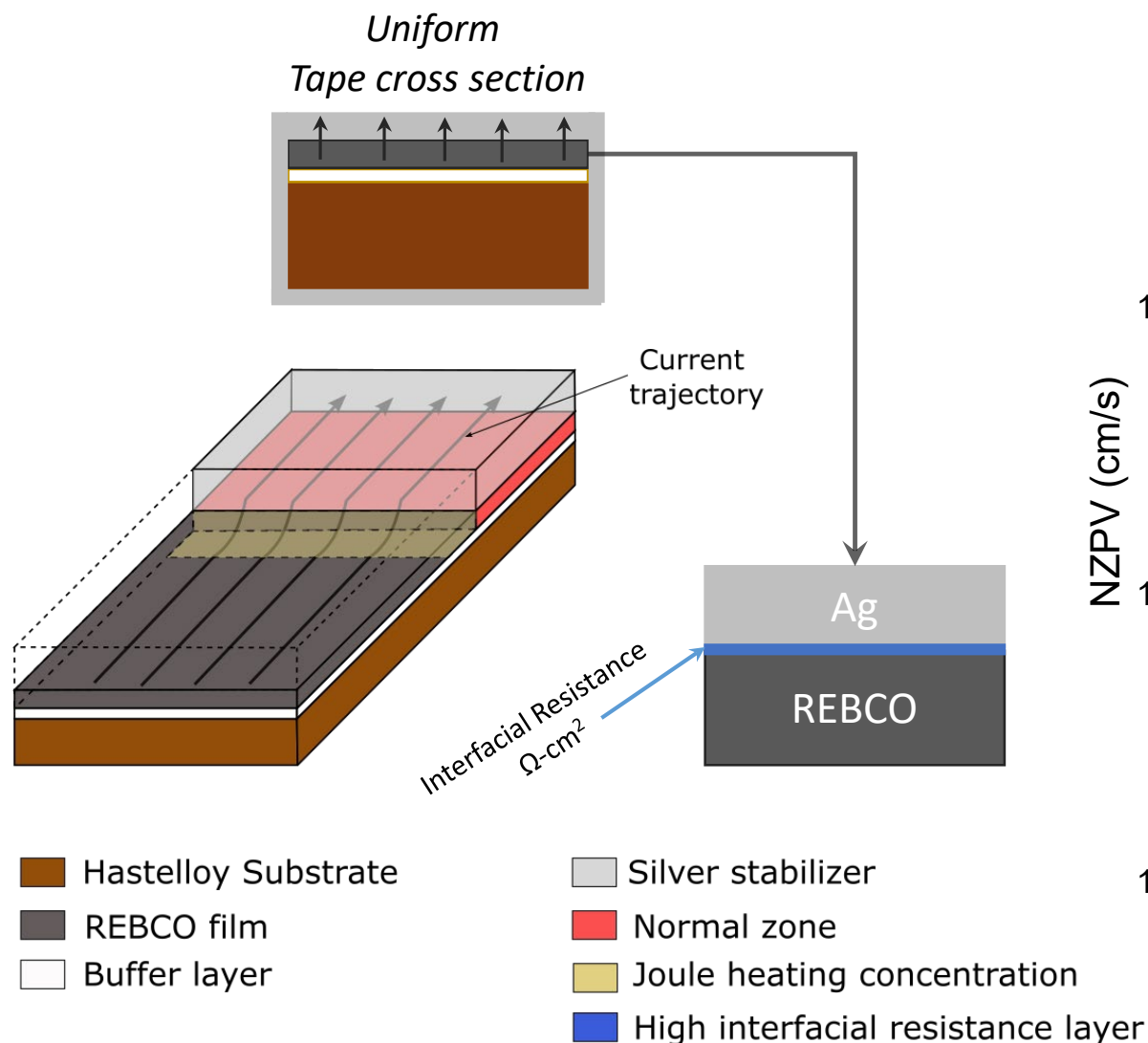
Video from Sebastian Hellmann – 3M-LS-02.7 – EUCAS 2015



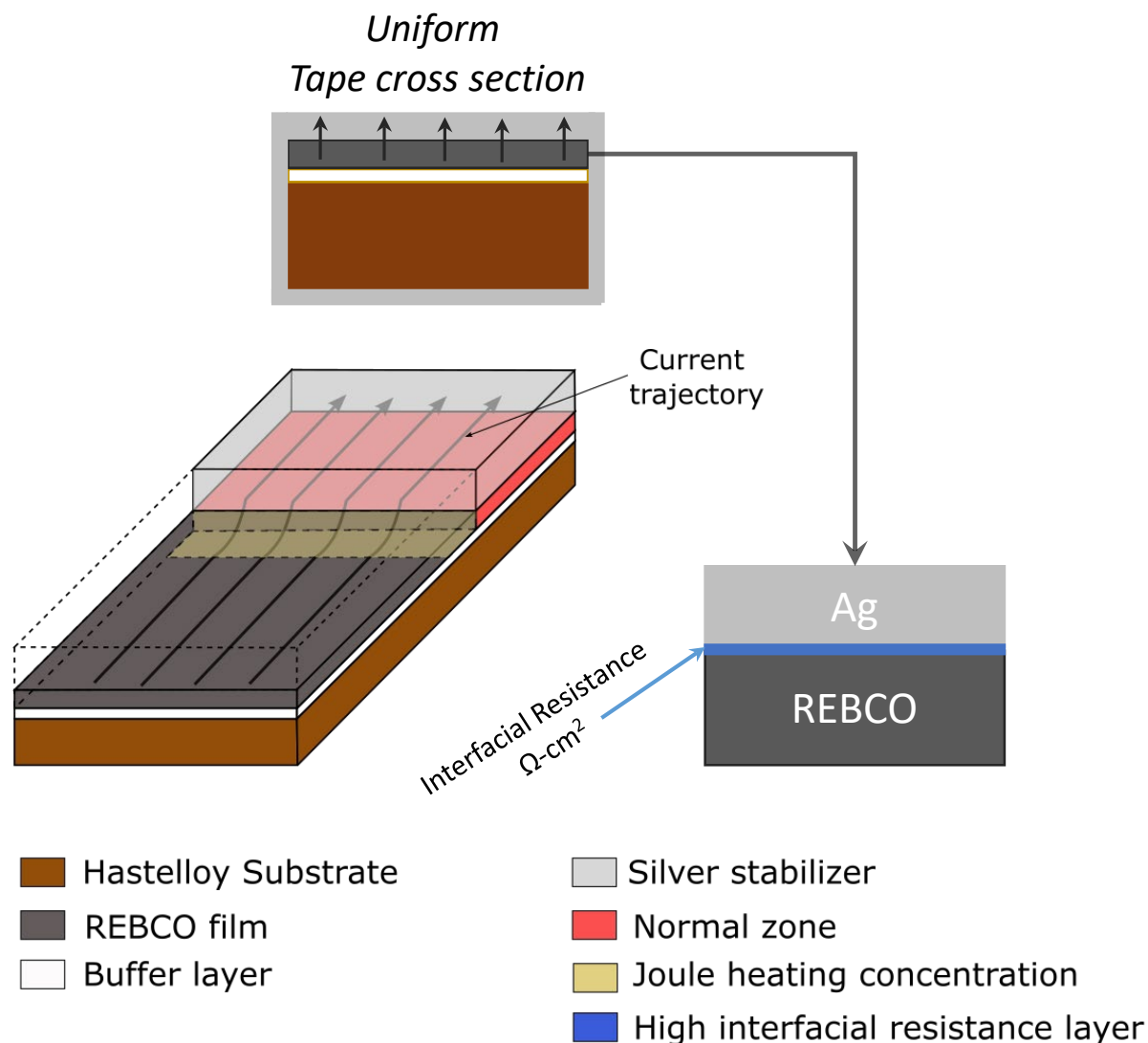
Superconductor 4mm, Superpower ReBCO-tape $40 \mu\text{m}$ Cu-stabilization



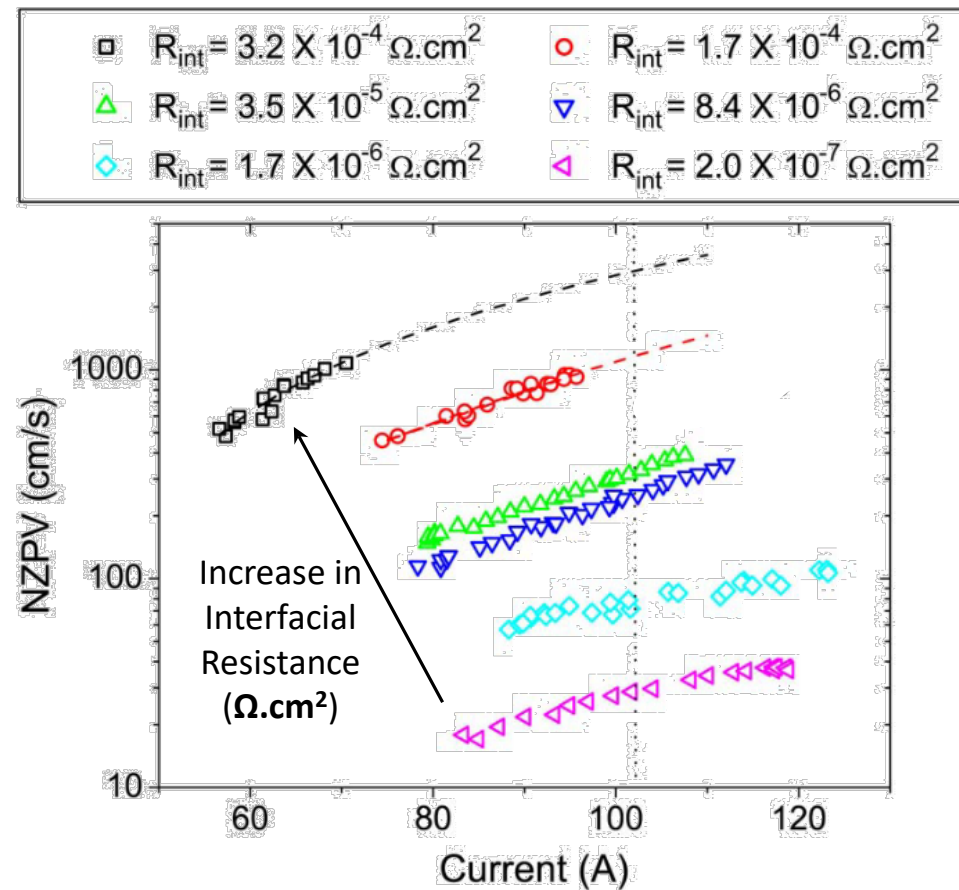
Motivation: Increasing the NZPV via the Interfacial Resistance



Motivation: Increasing the NZPV via the Interfacial Resistance

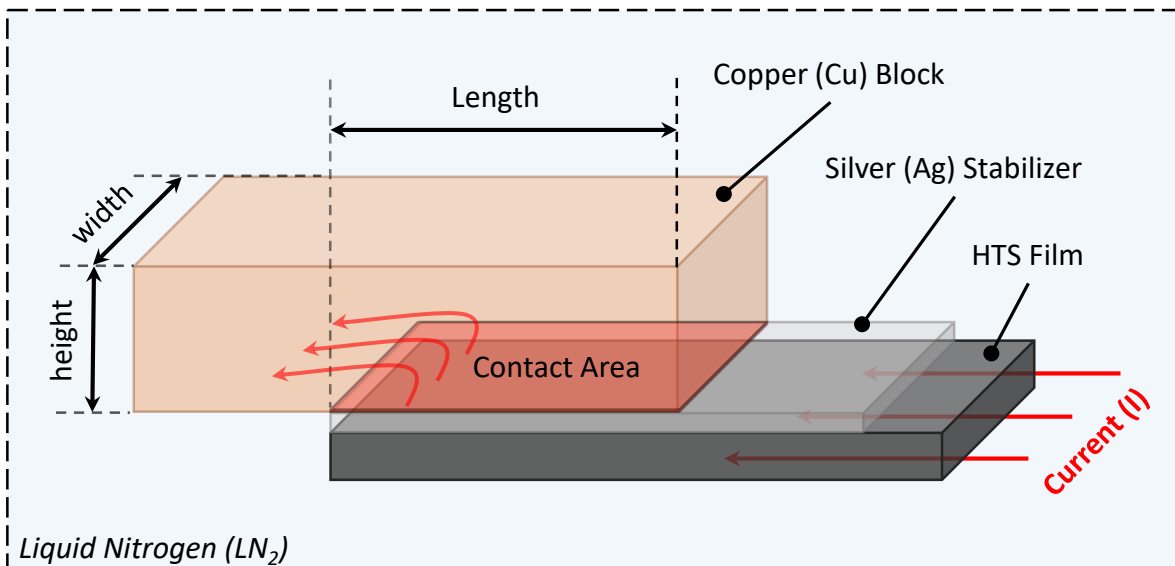


Lacroix et al., IEEE Trans. Supercond. Vol.23 No. 3 (2013)

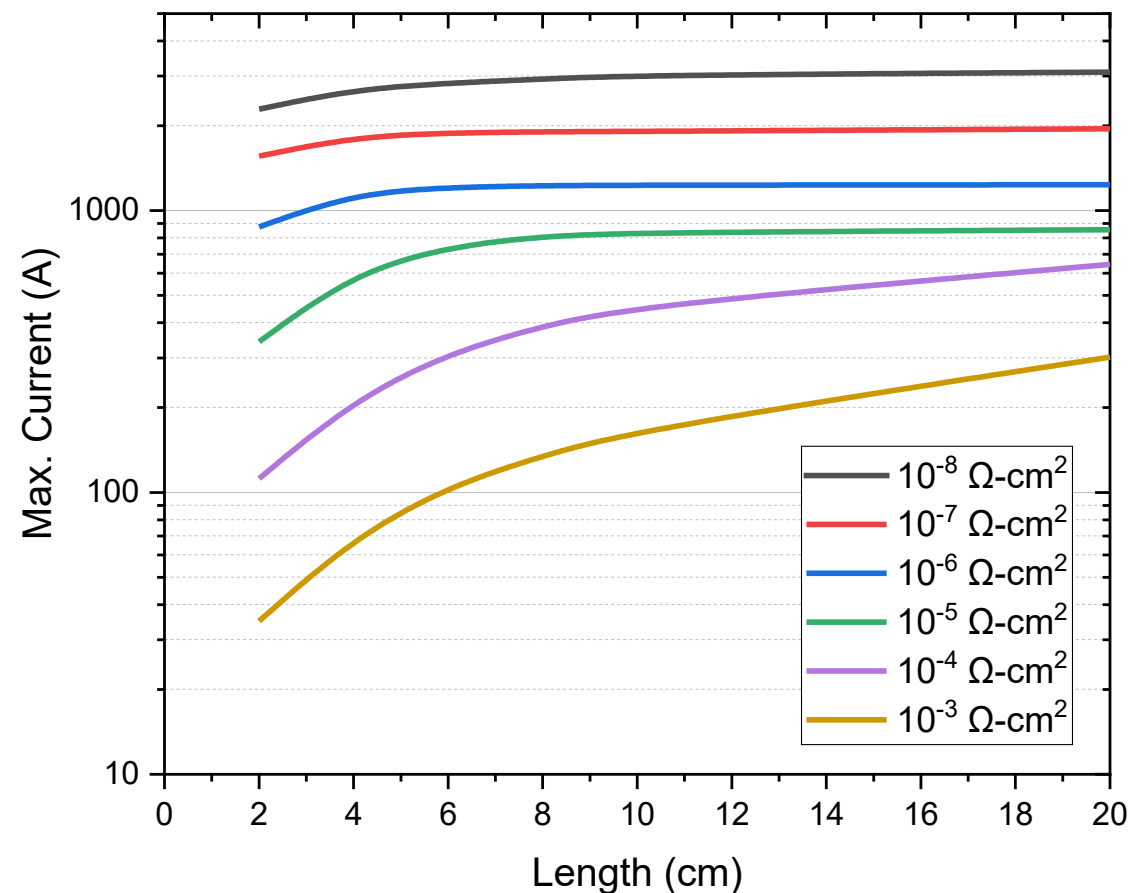


Motivation: Designing the Current Contacts Size

COMSOL



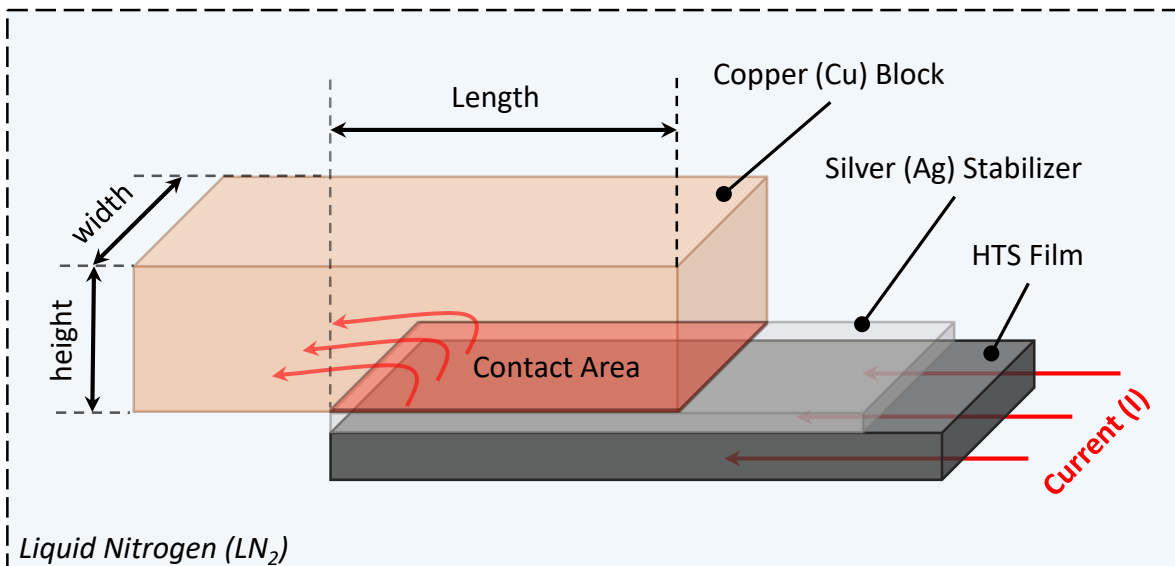
- Heights: $h_{Cu} = 1 \text{ cm}$, $h_{Ag} = 1 \mu\text{m}$, $h_{HTS} = 100 \text{ nm}$
- Width: $w_{Cu} = w_{Ag} = w_{HTS} = 12 \text{ mm}$
- Length sweep: $2 \leq L \leq 100 \text{ cm}$
- Transport Current sweep: $1 \leq I \leq 5000 \text{ A}$
- Interfacial Resistance : $10^{-8} \leq \rho \leq 10^{-3} \Omega\text{-cm}^2$
- Criteria for Min. Cont. Area: Maximum **decrease of 5% in I_c**



▲ **Current Contacts above 10 cm in length start to become impractical.**

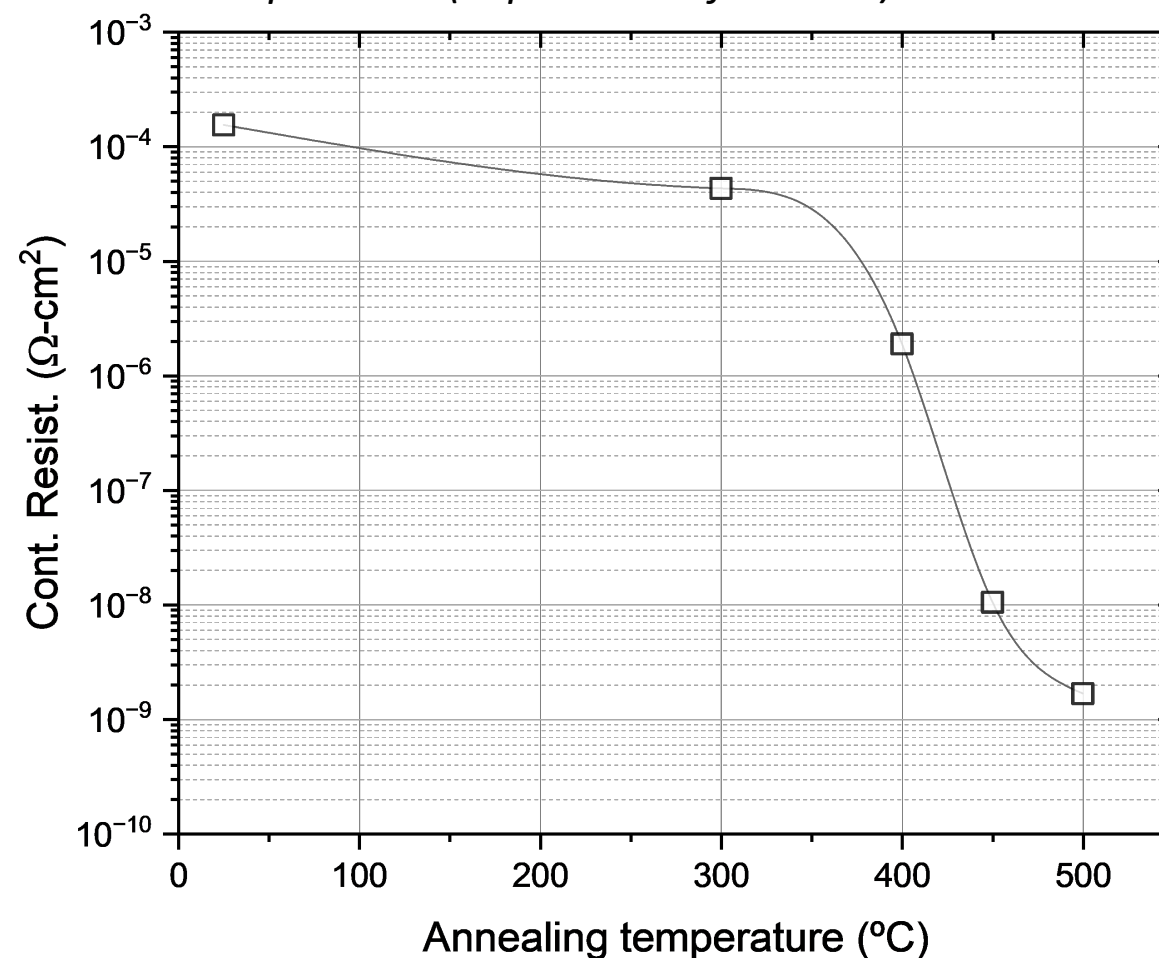
Motivation: Designing the Current Contacts Size

COMSOL



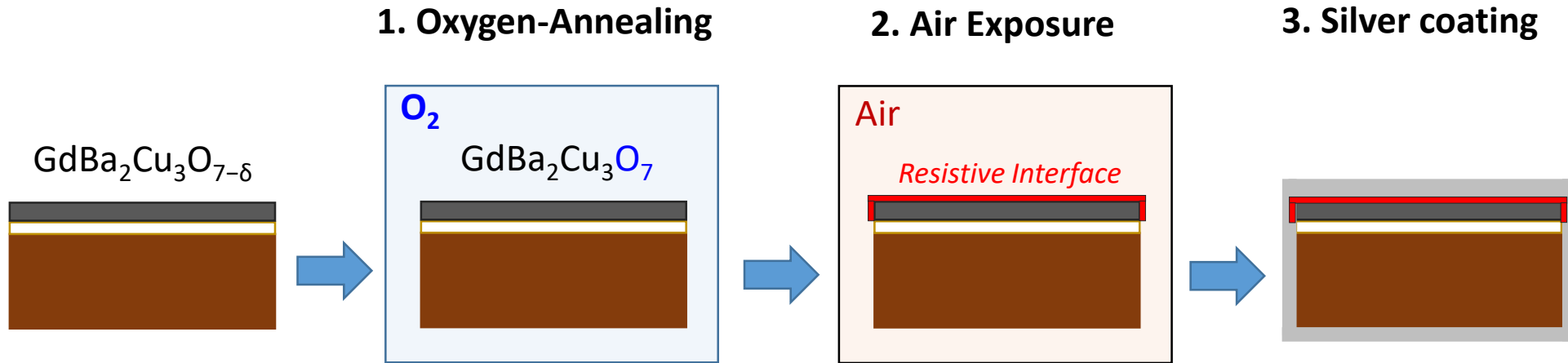
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Silver-GdBCO contact resistance versus Annealing temperature (T plateaus of 2 hours)

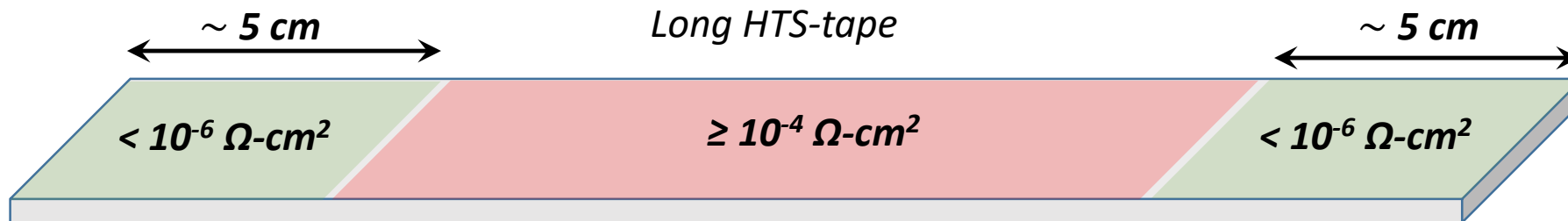


▲ **Current Contacts above 10 cm in length start to become impractical.**

1st Proposal: Local Annealing after air exposure



4. Local Oxygen-Annealing



P. Barusco et al. To be published



1st Proposal: Local Annealing – The Experiment

THEVA

HTS -tape of 10 cm

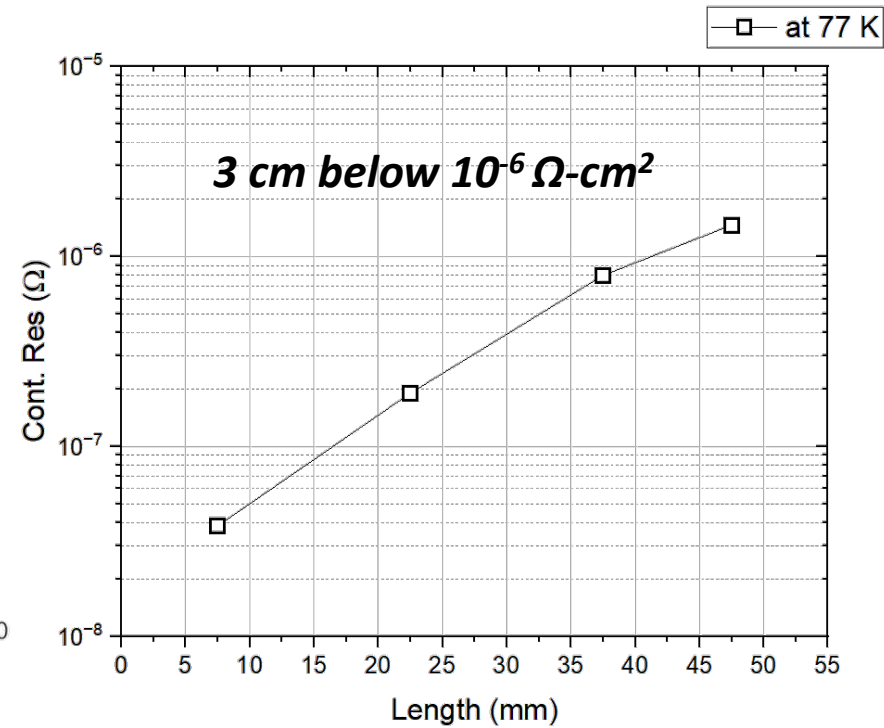
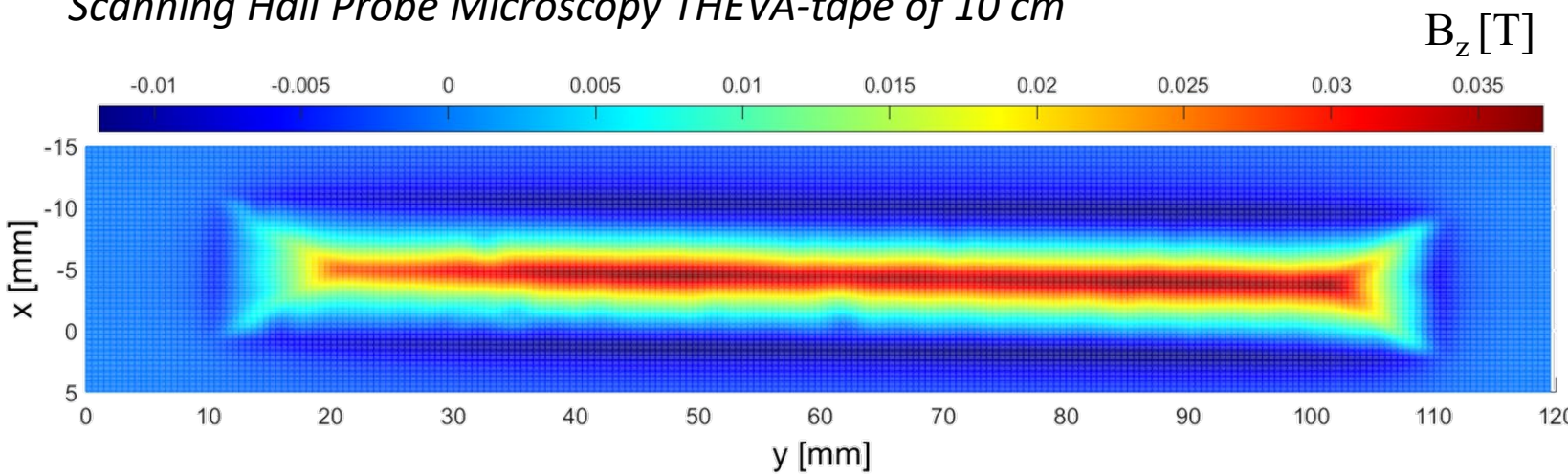
GdBCO film

~ 5 cm

Substrate tape

✓ Local Annealing at 500 °C for 2h in 0.6 L/min of O₂ flow

Scanning Hall Probe Microscopy THEVA-tape of 10 cm





1st Proposal: Local Annealing – The Experiment

THEVA

HTS -tape of 10 cm

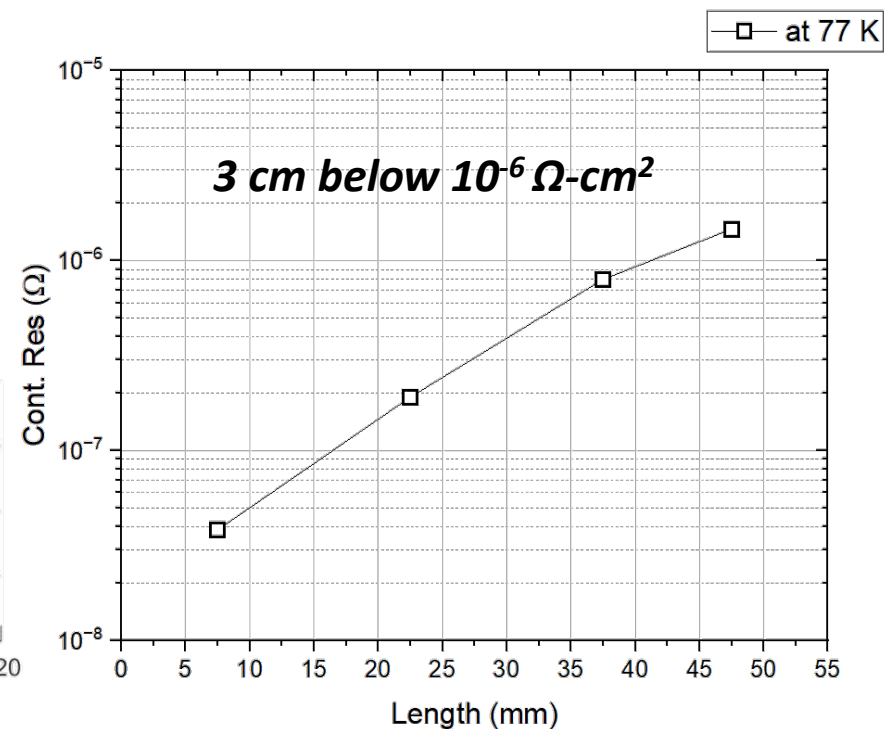
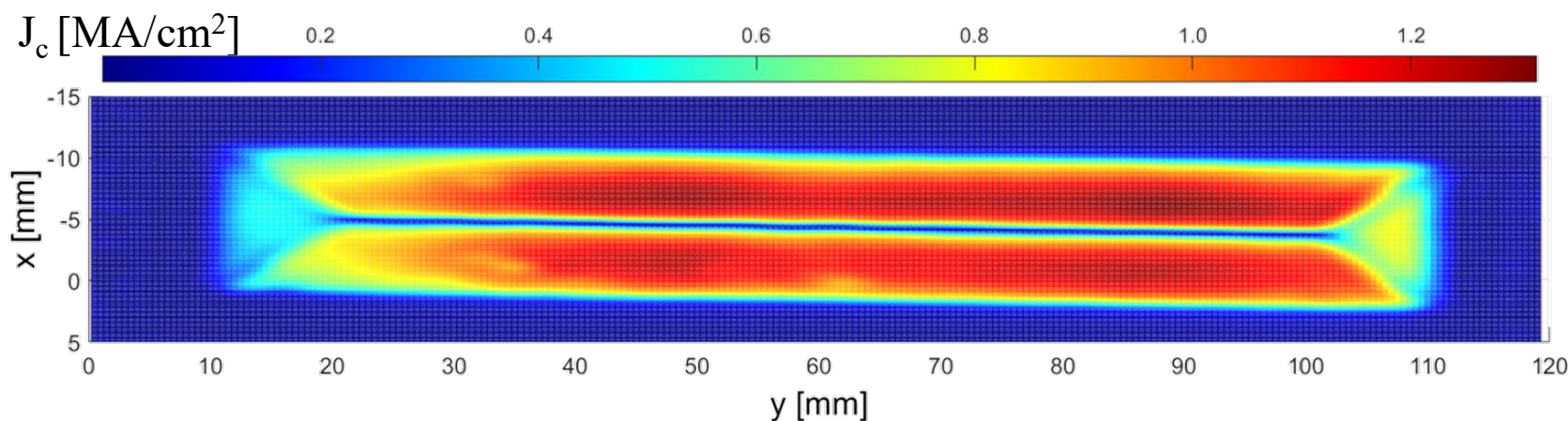
GdBCO film

~ 5 cm

Substrate tape

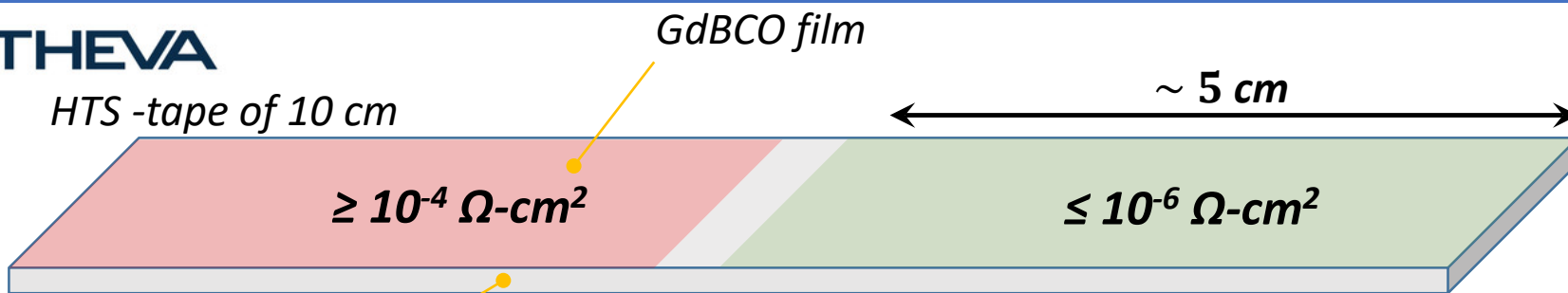
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Scanning Hall Probe Microscopy THEVA-tape of 10 cm



1st Proposal: Local Annealing – The Experiment

THEVA

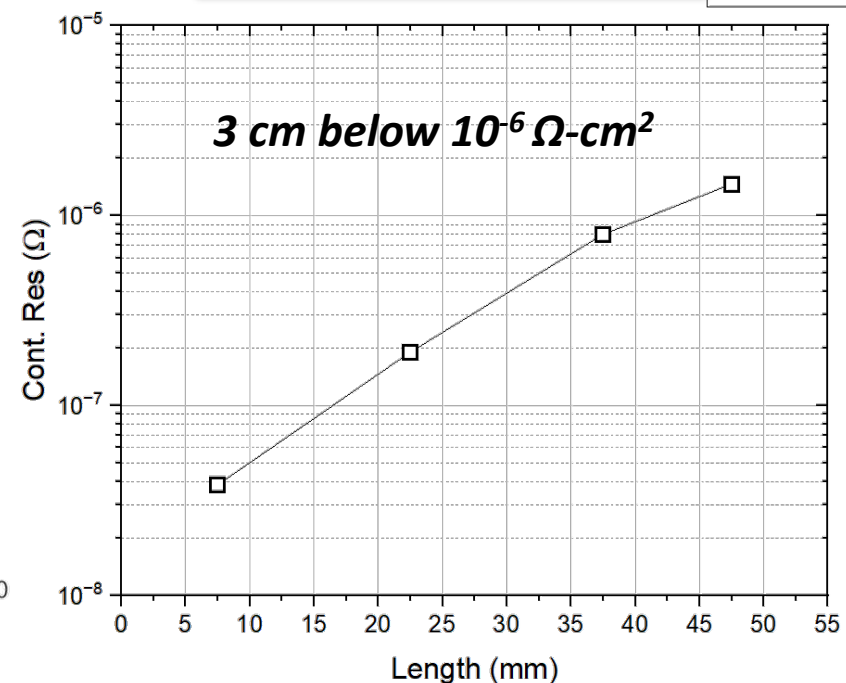
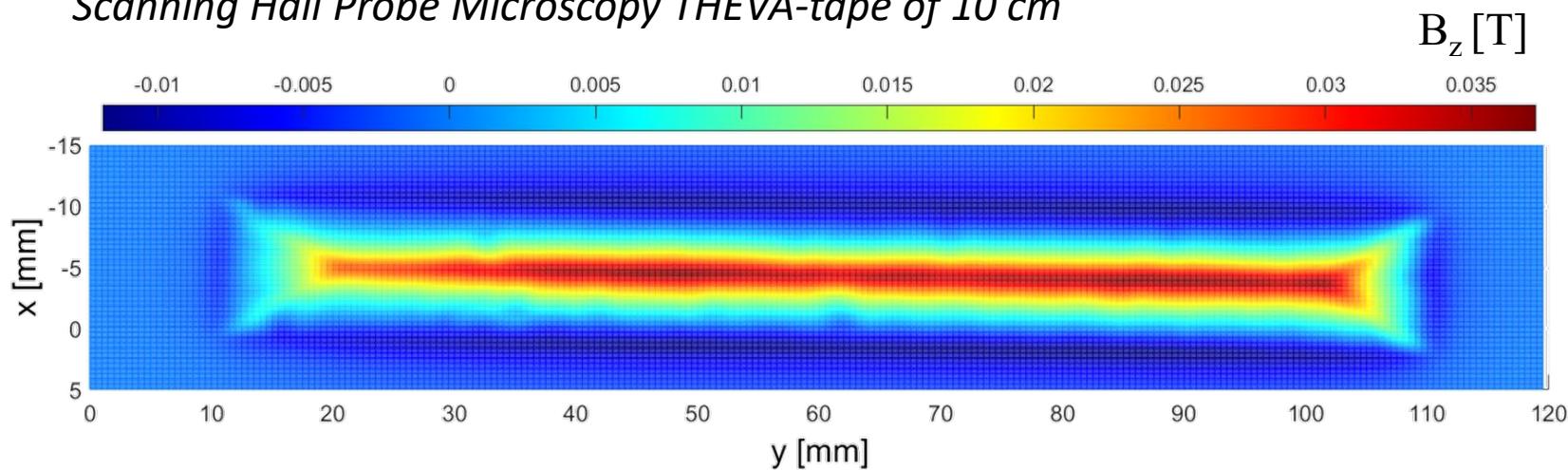


Substrate tape ✓ Local Annealing at 500 °C for 2h in 0.6 L/min of O₂ flow



□ at 77 K

Scanning Hall Probe Microscopy THEVA-tape of 10 cm





Lacroix et al., SUST 27 035003 (2014)
Lacroix et al., SUST 27 055013 (2014)
Lacroix et al., SUST 30 064004 (2017)

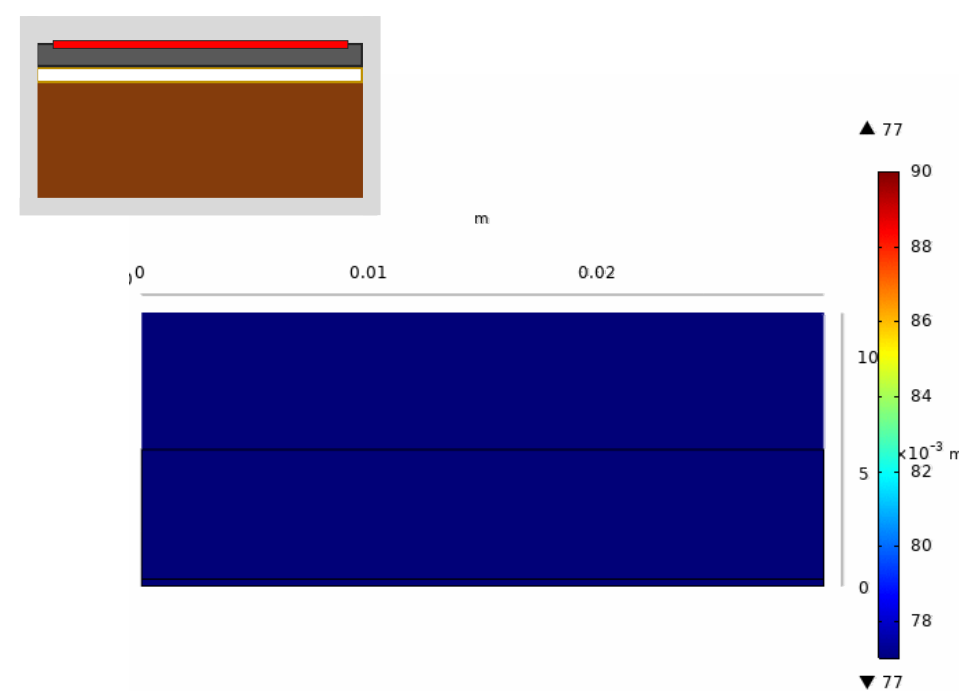
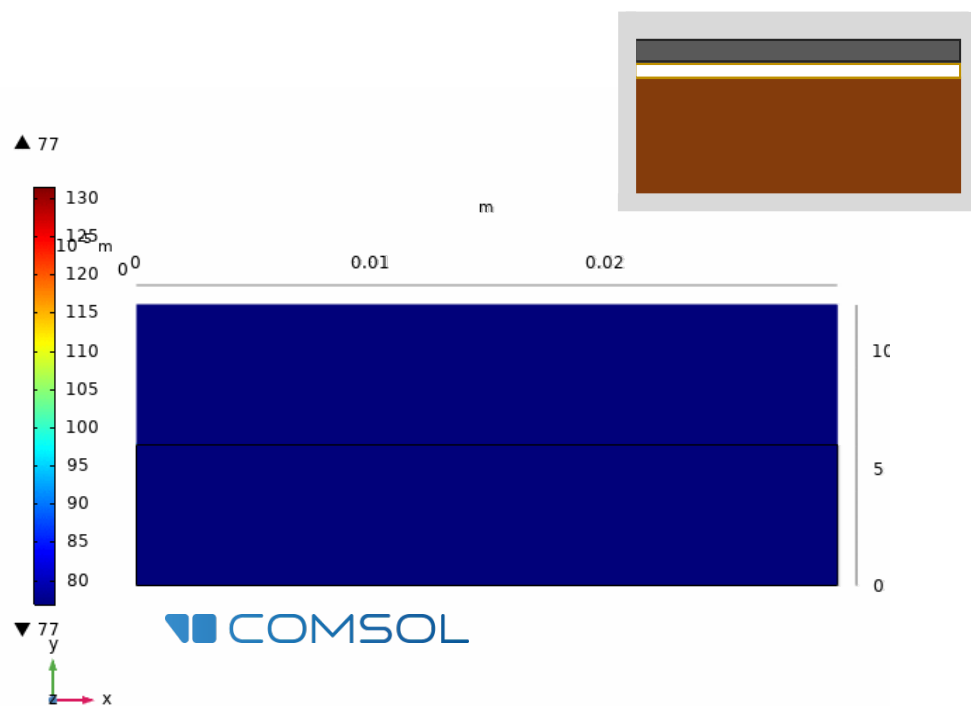
2nd Proposal: The Current Flow Diverter (CFD)

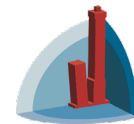
Uniform Interface vs. CFD

- Steady current 300 A
- For 10 ms Duration

- Hastelloy Substrate
- REBCO film
- Buffer layer

- Silver stabilizer
- Normal zone
- Joule heating concentration
- High interfacial resistance layer



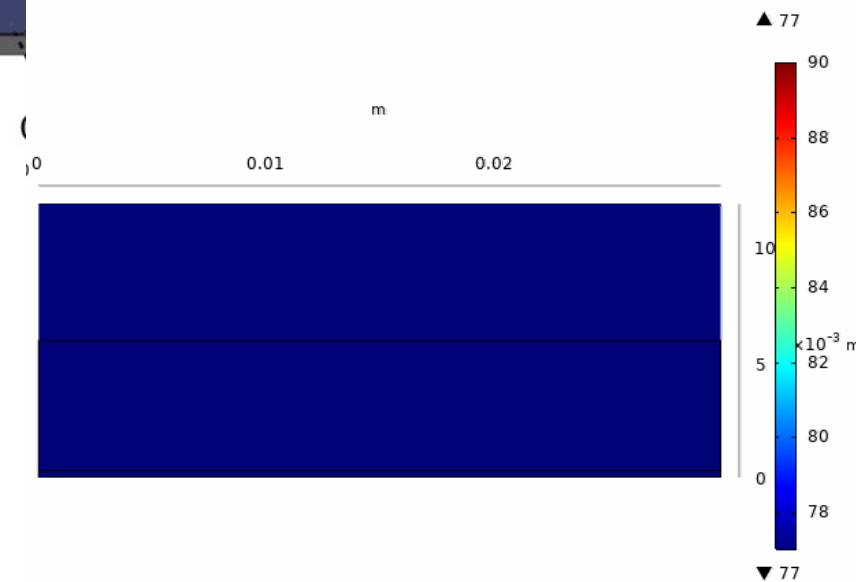
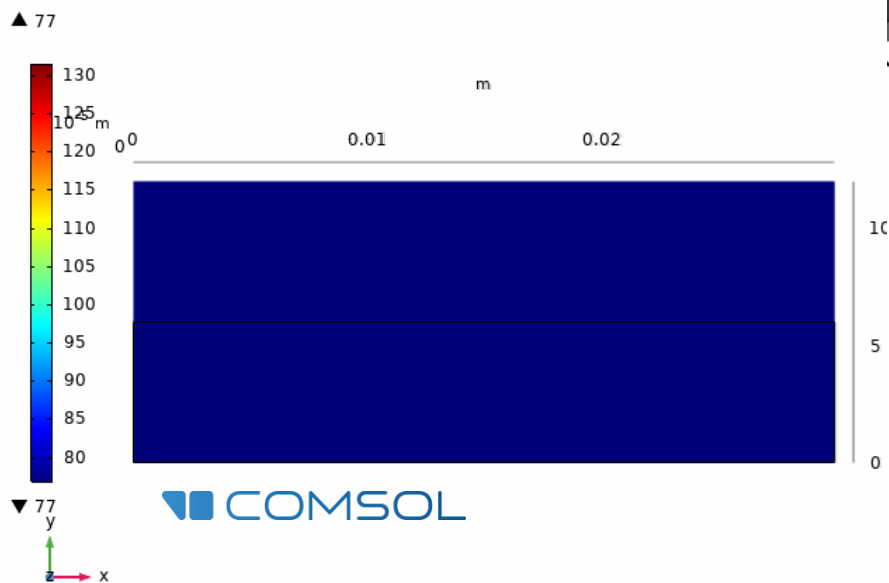
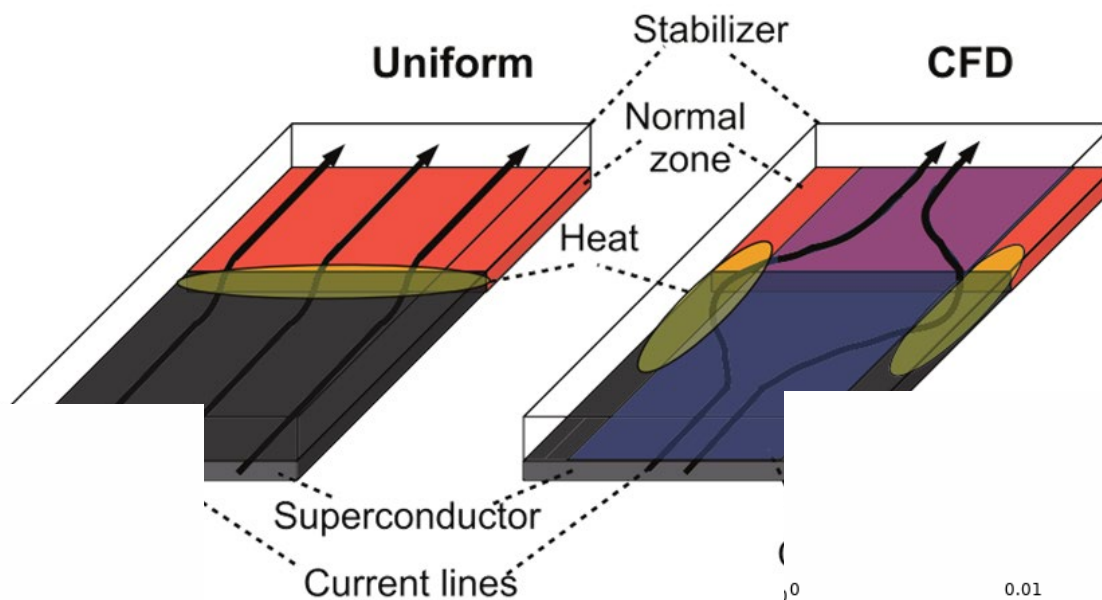


Lacroix et al., SUST 27 035003 (2014)
Lacroix et al., SUST 27 055013 (2014)
Lacroix et al., SUST 30 064004 (2017)

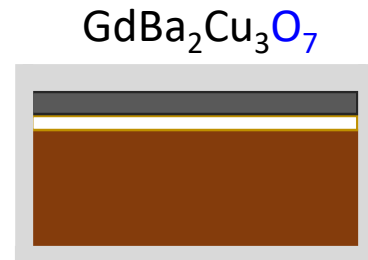
2nd Proposal: The Current Flow Diverter (CFD)

Uniform Interface vs. CFD

- Steady current 300 A
- For 10 ms Duration



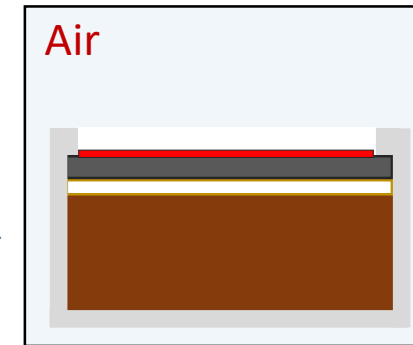
1. Commercial Ag coated tape



2. Partial Silver Etch



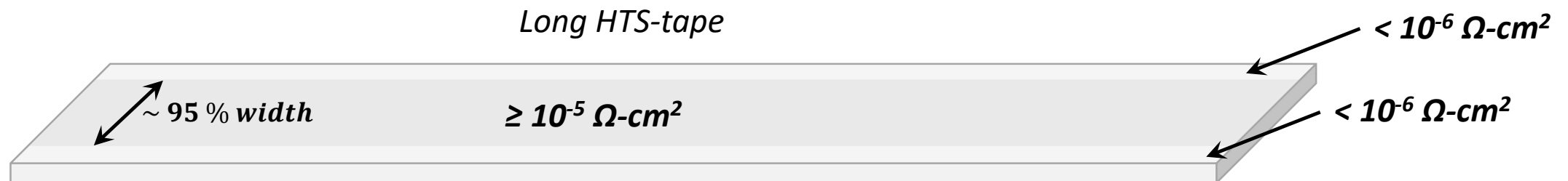
3. Surface Passivation

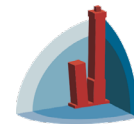


4. Re-deposition of Silver

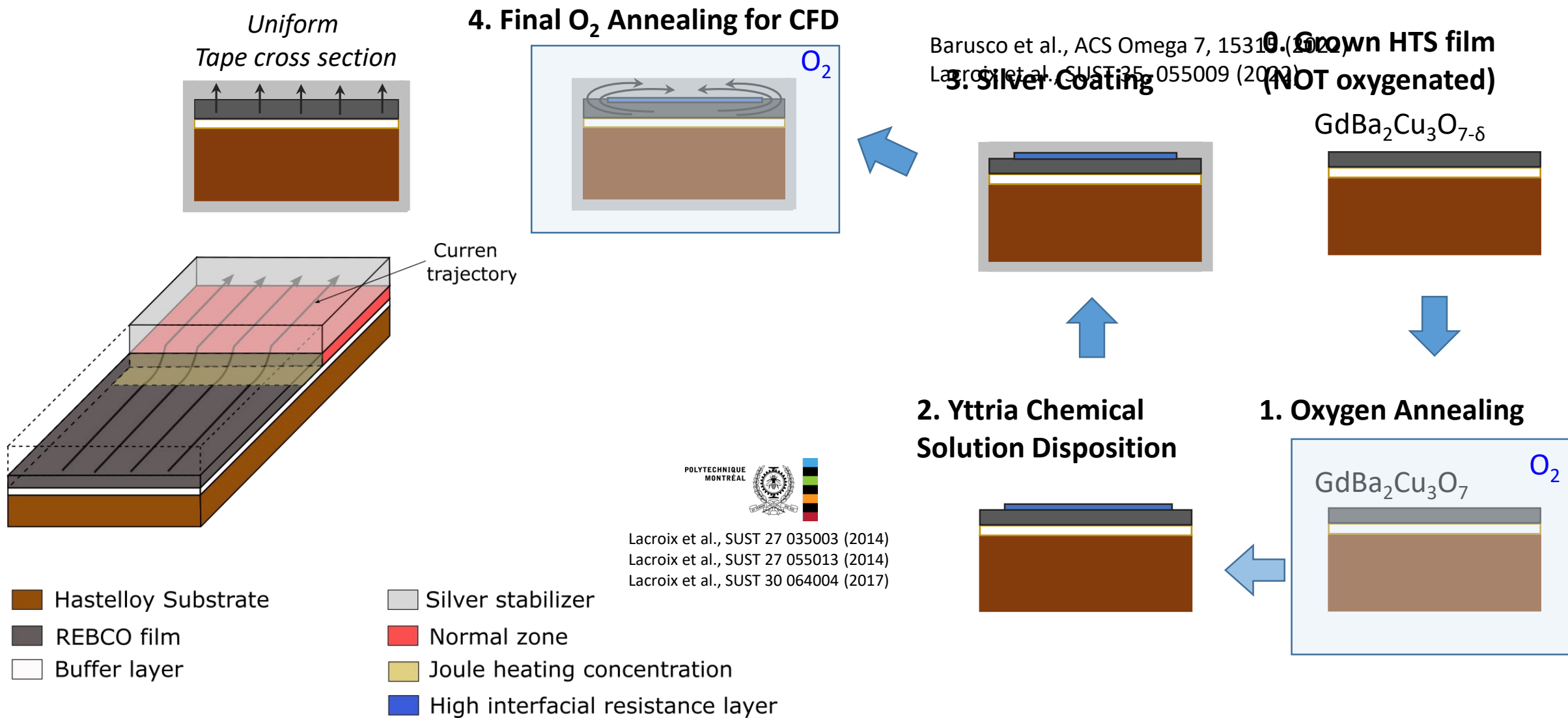


4. Final CFD





2nd Proposal: CFD with Amorphous Y_2O_3

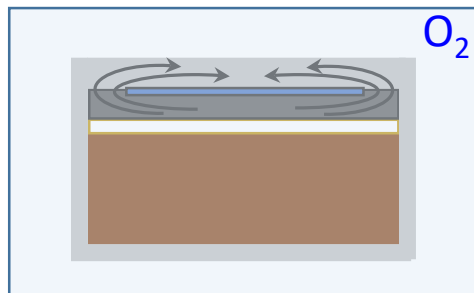
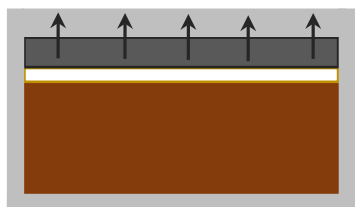




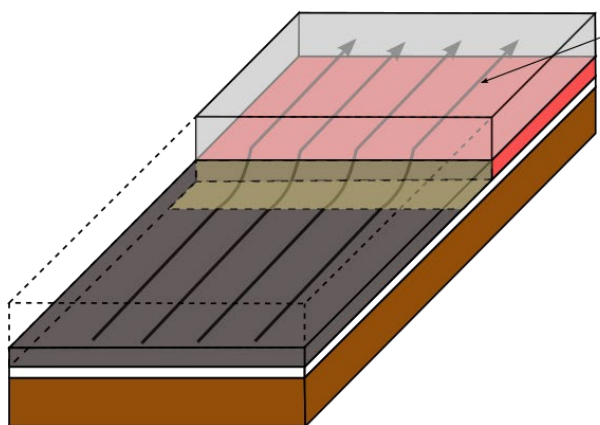
2nd Proposal: CFD with Amorphous Y₂O₃

4. Final O₂ Annealing for CFD

Uniform
Tape cross section

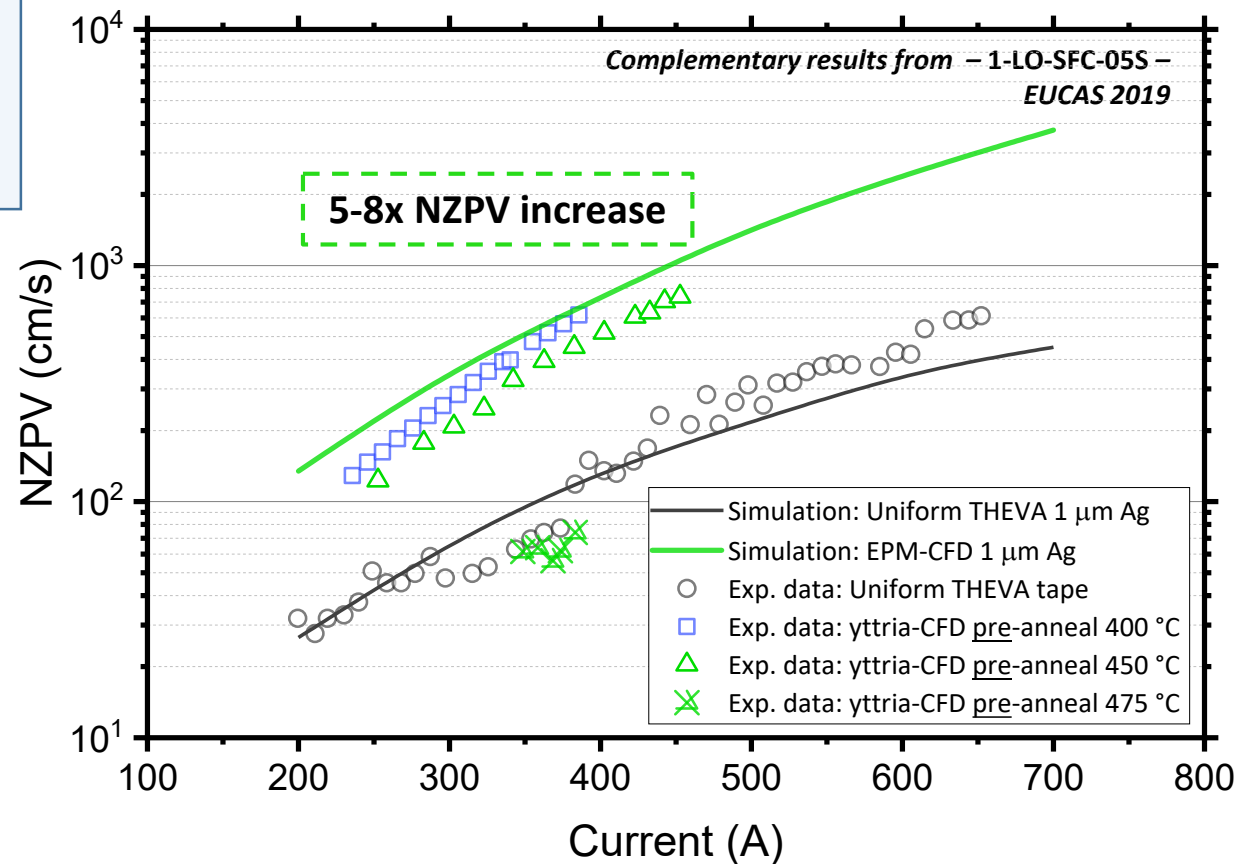


Current
trajectory



- Hastelloy Substrate
- REBCO film
- Buffer layer

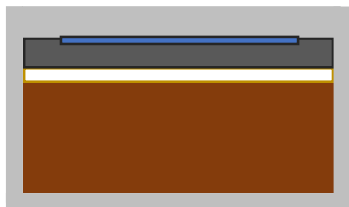
- Silver stabilizer
- Normal zone
- Joule heating concentration
- High interfacial resistance layer



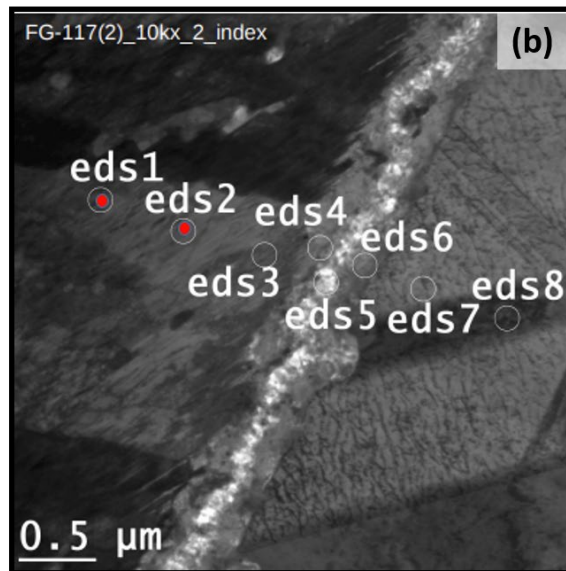
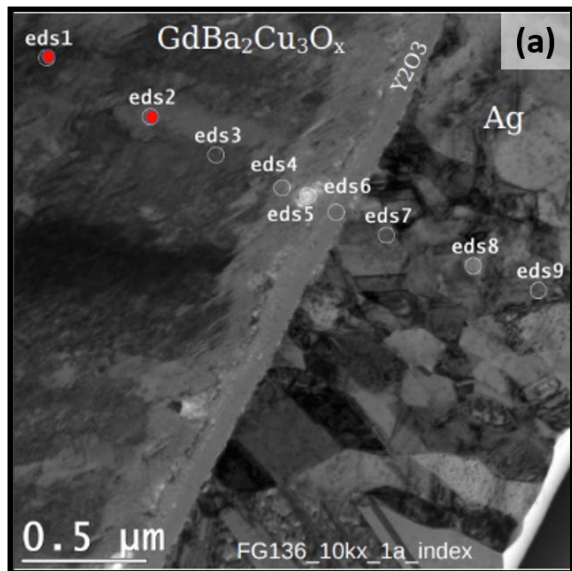
Lacroix et al., SUST 27 035003 (2014)
 Lacroix et al., SUST 27 055013 (2014)
 Lacroix et al., SUST 30 064004 (2017)

2nd Proposal: TEM analysis of the Yttria-CFD interface

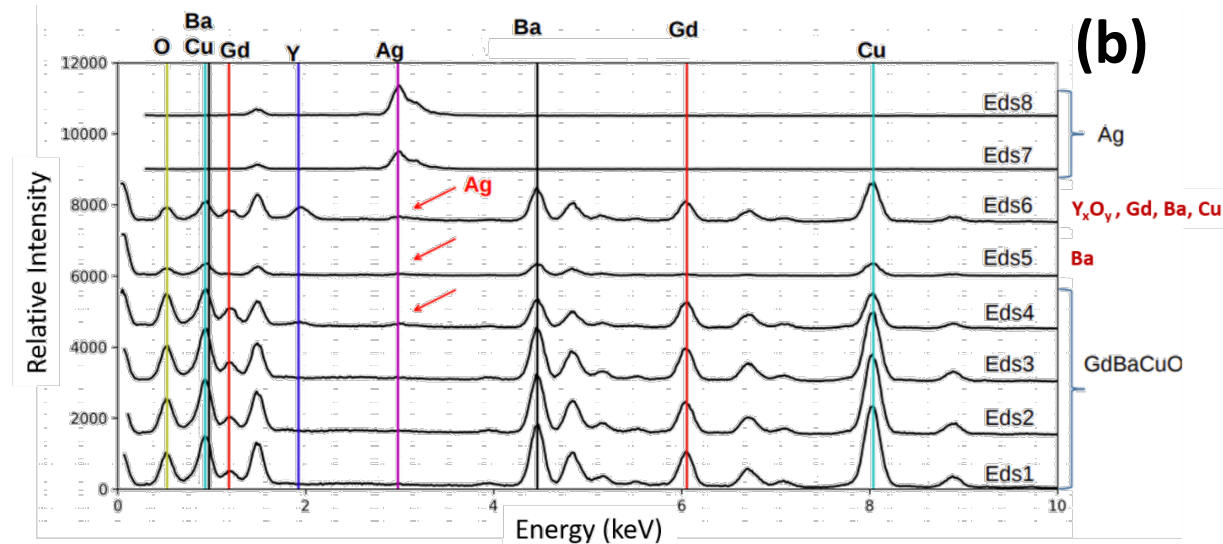
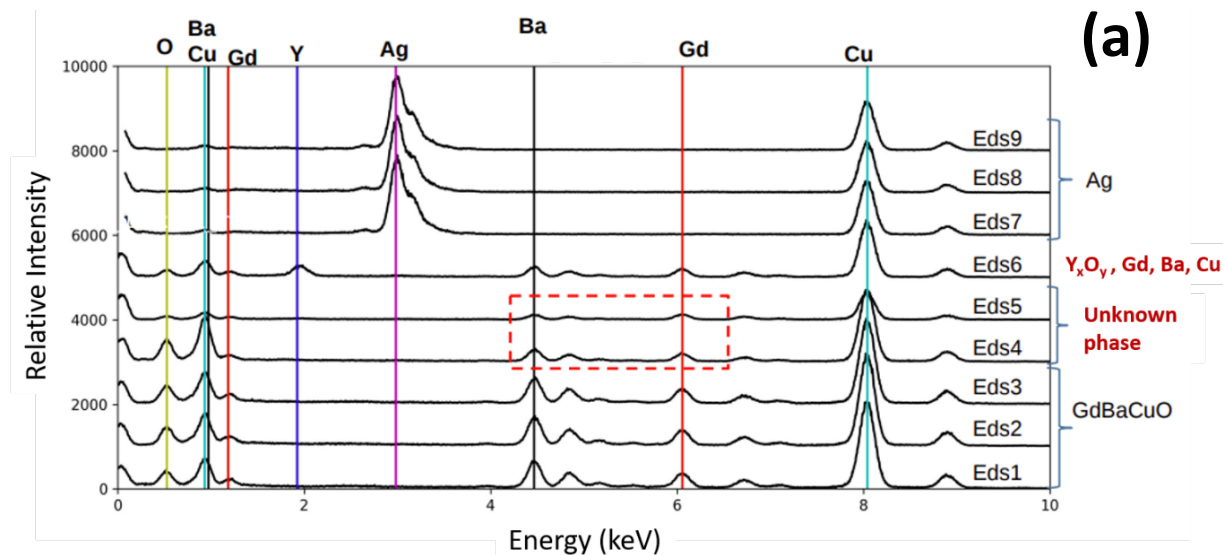
**Yttria-CFD Before
Oxygen Annealing**



**Yttria-CFD After
Oxygen Annealing**

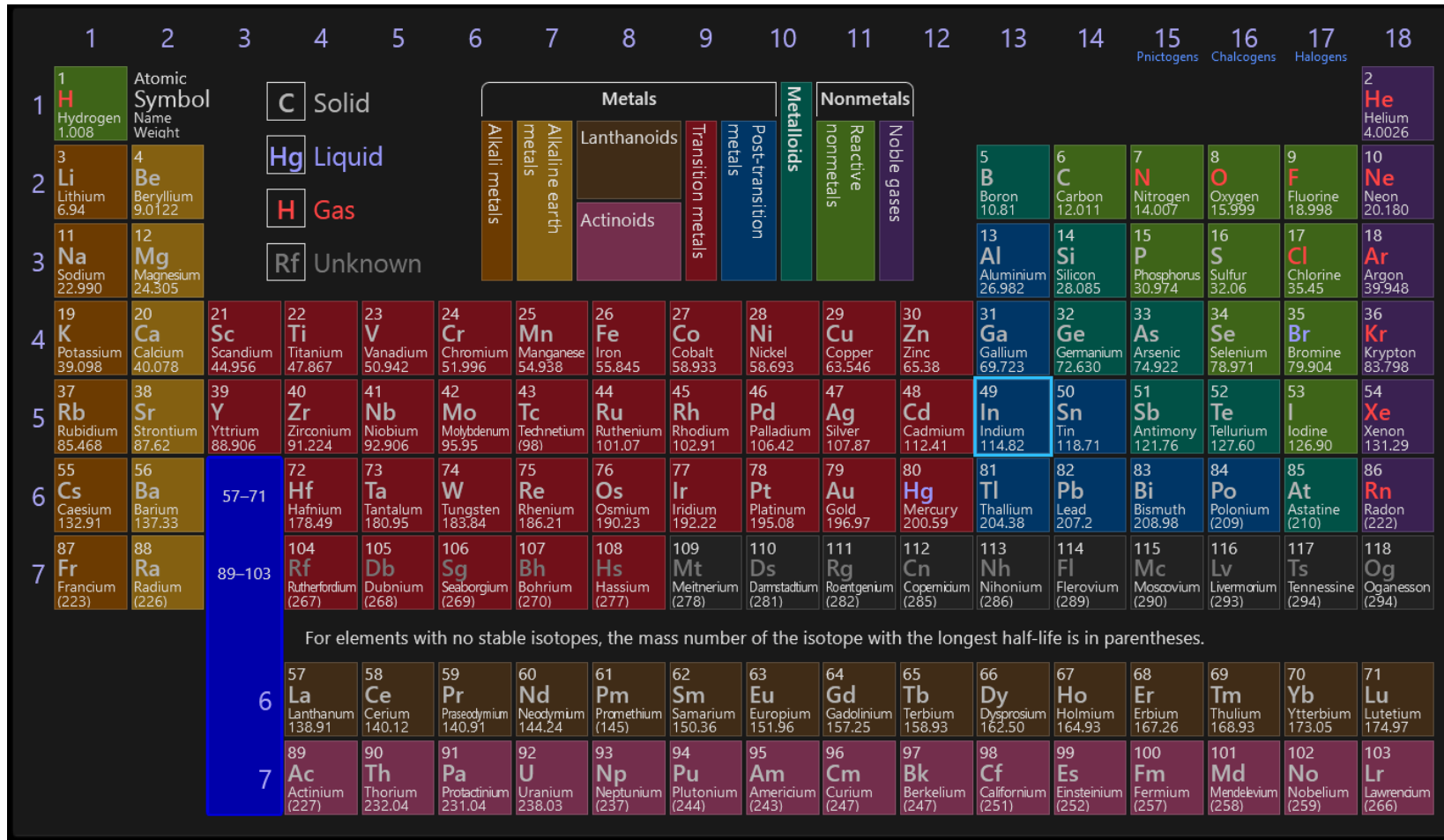


Barusco et al., ACS Omega 7, 15315 (2022)



3rd Proposal: CFD with intermetallic compounds (IMC)

V. Simić and Z. Marinković, “Room Temperature Interactions in Ag-Metals Thin Film Couples”, *Thin Solid Films*, 61 (1979) 149-160

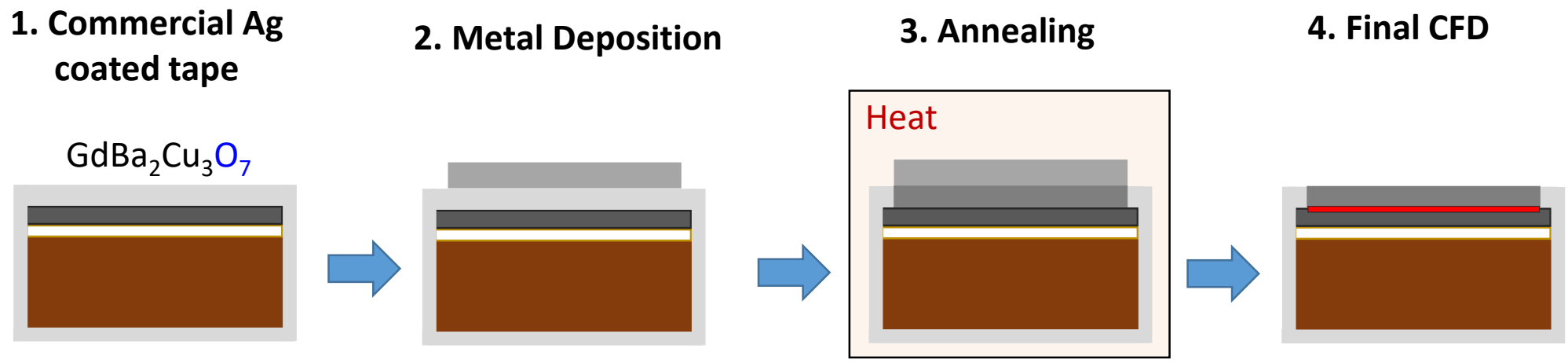


Periodic table showing elements grouped by physical state and chemical categories. Legend: **C** Solid, **Hg** Liquid, **H** Gas, **Rf** Unknown. Categories: Alkali metals, Alkaline earth metals, Lanthanoids, Actinoids, Transition metals, Post-transition metals, Metalloids, Reactive nonmetals, Noble gases. Groups: Pnictogens (15), Chalcogens (16), Halogens (17).

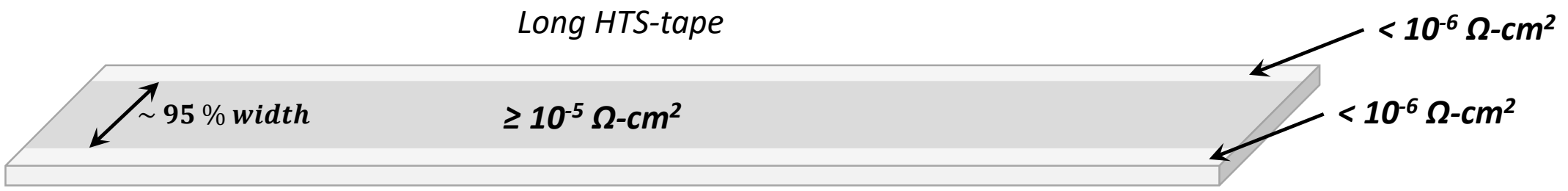
For elements with no stable isotopes, the mass number of the isotope with the longest half-life is in parentheses.

Binary System Ag and ...	Bulk difusion	Thin film interdiffusion at Room T
Al	+	-
Au	-	-
Bi	-	-
Cd	+	+
Cr	-	-
Cu	-	-
Ga	+	+
In	+	+
Pb	-	-
Sn	+	+

3rd Proposal: Can we use another metal to create the CFD?






4. Final CFD



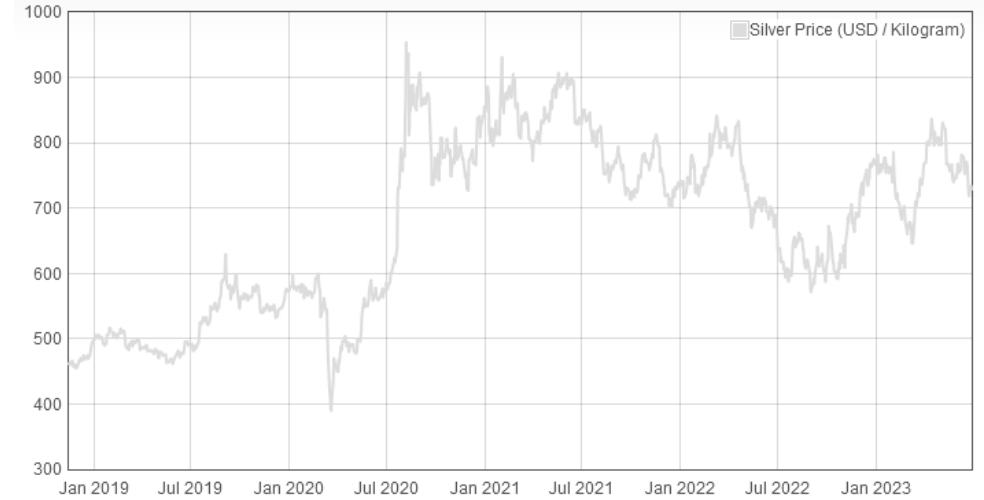
3rd Proposal: CFD with Indium (In)

Indium

atomic number	49	114.818	atomic weight
symbol	In		acid-base properties of higher-valence oxides
electron configuration	[Kr]4d ¹⁰ 5s ² 5p ¹		crystal structure
name	indium		physical state at 20 °C (68 °F)

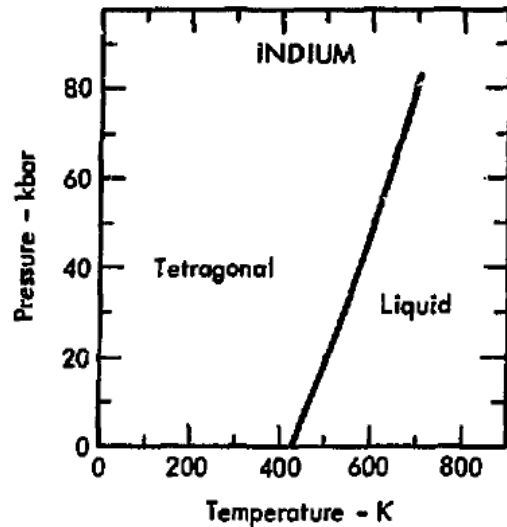


Vacuum Seal with In sheet

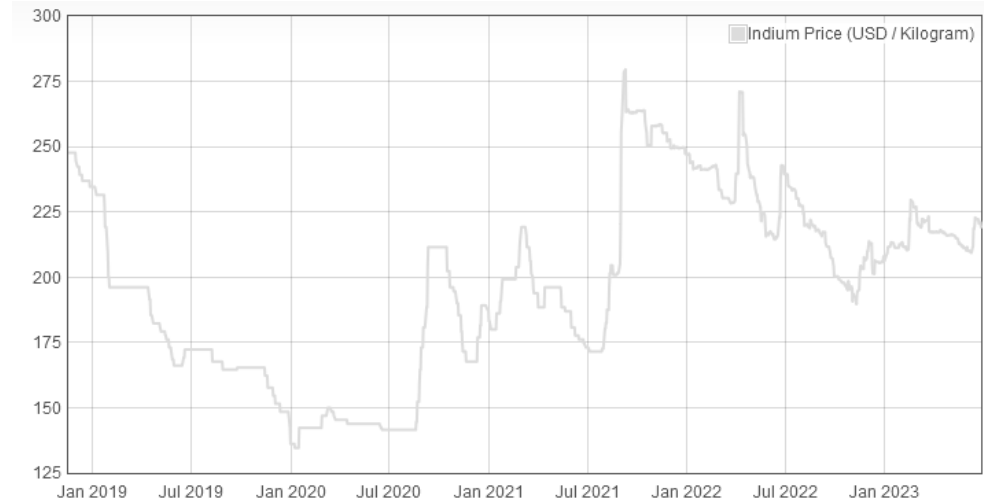
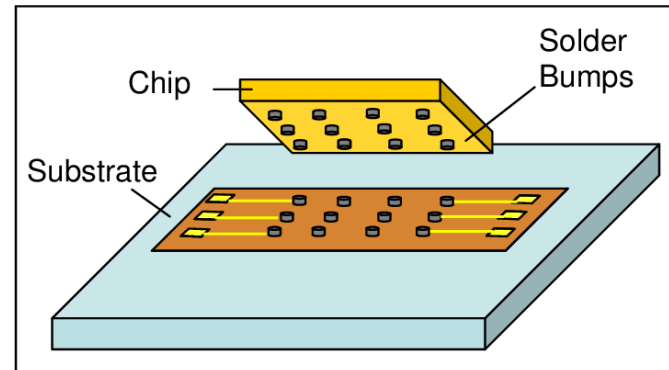


	Other metals		Solid
	Tetragonal		Equal relative strength

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In flip-chip bonding



3rd Proposal: How much Indium do we need?

A.N. Campbell, *Canadian Journal of Chemistry*. 48(11): 1703-1715.

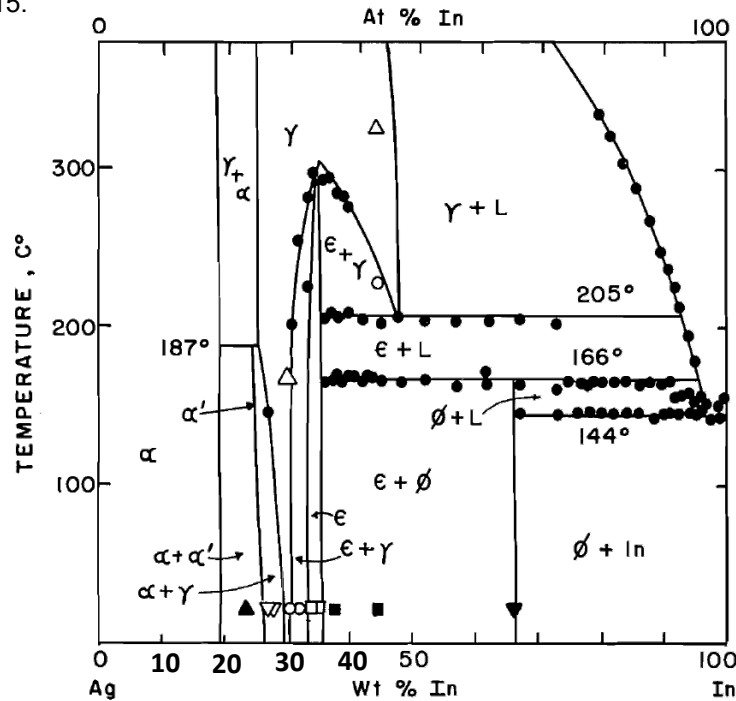
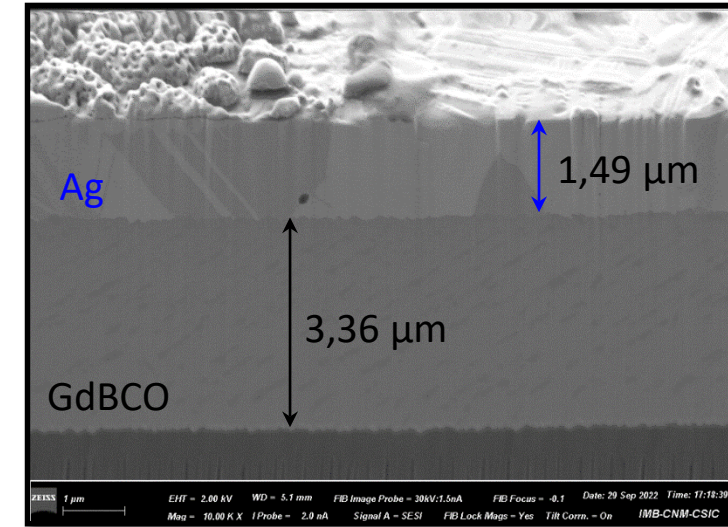
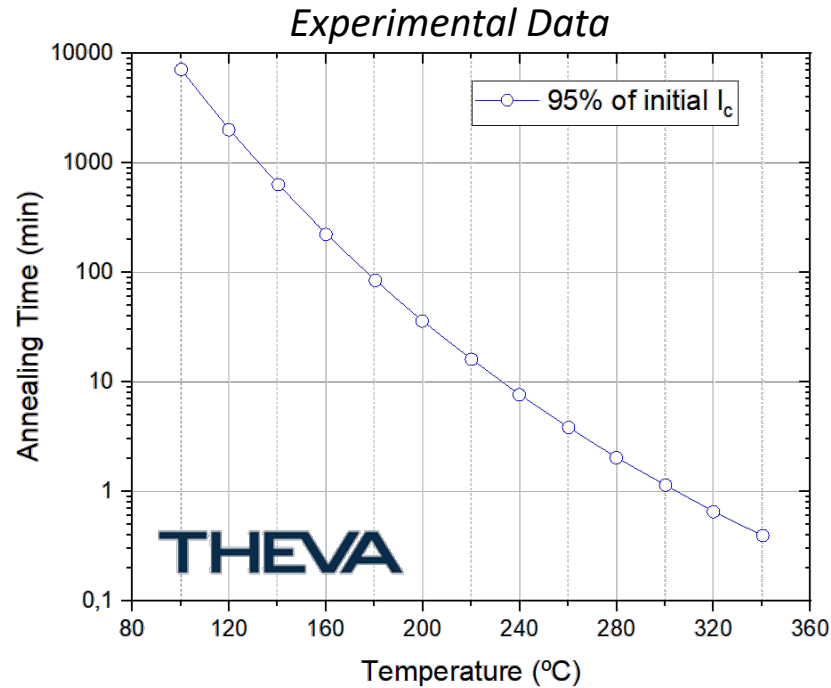


FIG. 5. Phase diagram of Ag-In below 300 °C: ▽, $\alpha + \gamma$; ○, $\epsilon + \gamma$; □, ϵ ; ■, $\epsilon + \phi$; △, γ ; ▲, $\alpha + \alpha'$ (γ phase metastable); ▼, ϕ ; ●, DTA.



SEM-FIB cross-section image of THEVA tape

- BCT AgIn_2 (ϕ -phase) \rightarrow ;
- Cubic Ag_2In (ϵ -phase) \rightarrow 32,8 wt% - 36,82wt%
- Hexagonal Ag_3In (γ -phase) \rightarrow 29 wt% - 29.7 wt%
- Cubic Ag_3In (α' -phase, aka alpha-prime)

⚠ The AgIn_2 has a high Ductility coefficient. Unsuitable for the HTS's shunt coating.

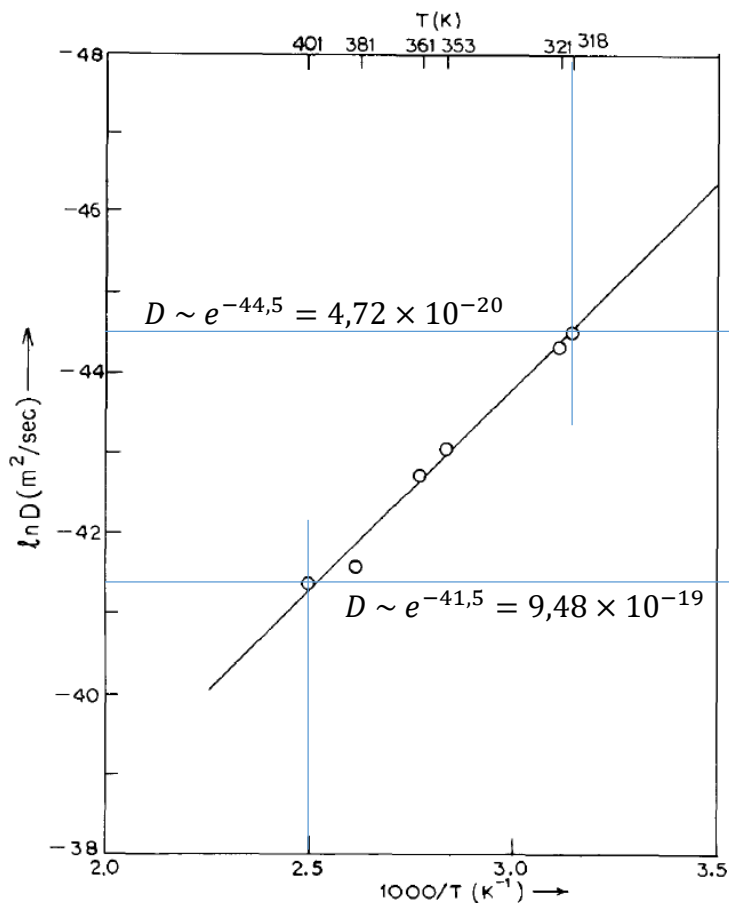
1) Pure Ag_2In (ϵ -phase)

2) $\text{Ag}_3\text{In} + \text{Ag}_2\text{In}$ phase ($\epsilon + \gamma$)

3) Pure Ag_3In (γ -phase)

3rd Proposal: How fast Indium Diffuses in pure Silver?

R. Roy, "The kinetics of formation of Intermetallics in In/Ag thin film couples", *Thin Solid Films*, **197**(1991) 303-318

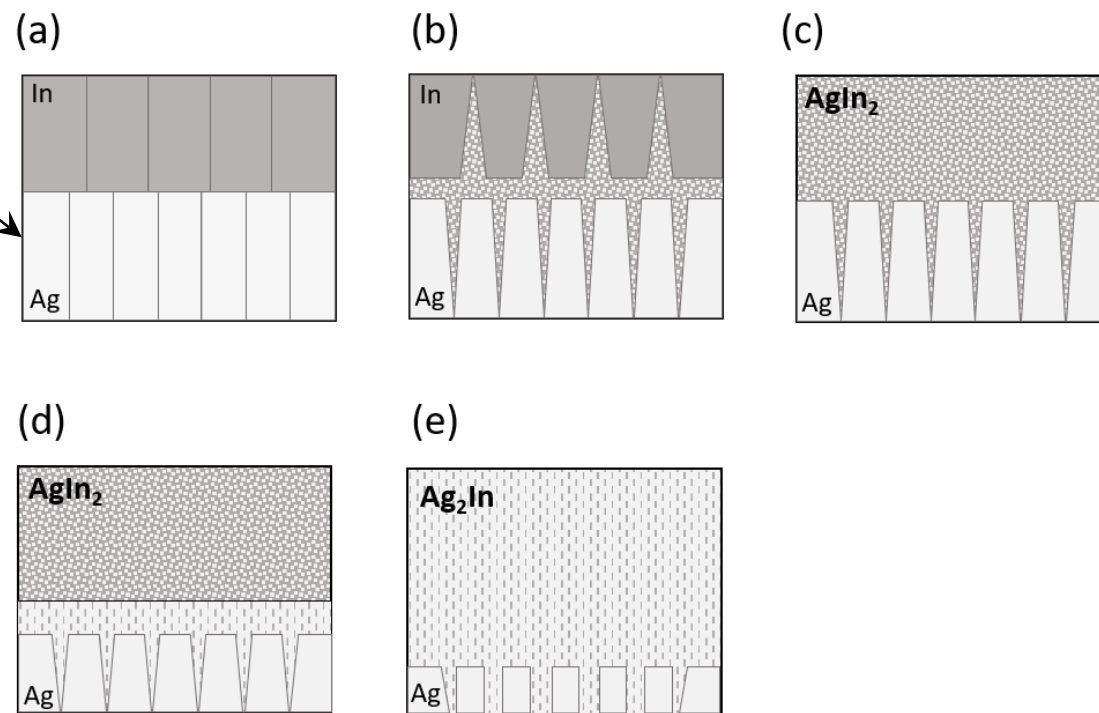


$$L = 1 \mu\text{m}$$

$$\tau = \frac{L^2}{2\pi^2 D}$$

$\tau = 298 \text{ h} = 12 \text{ days}$

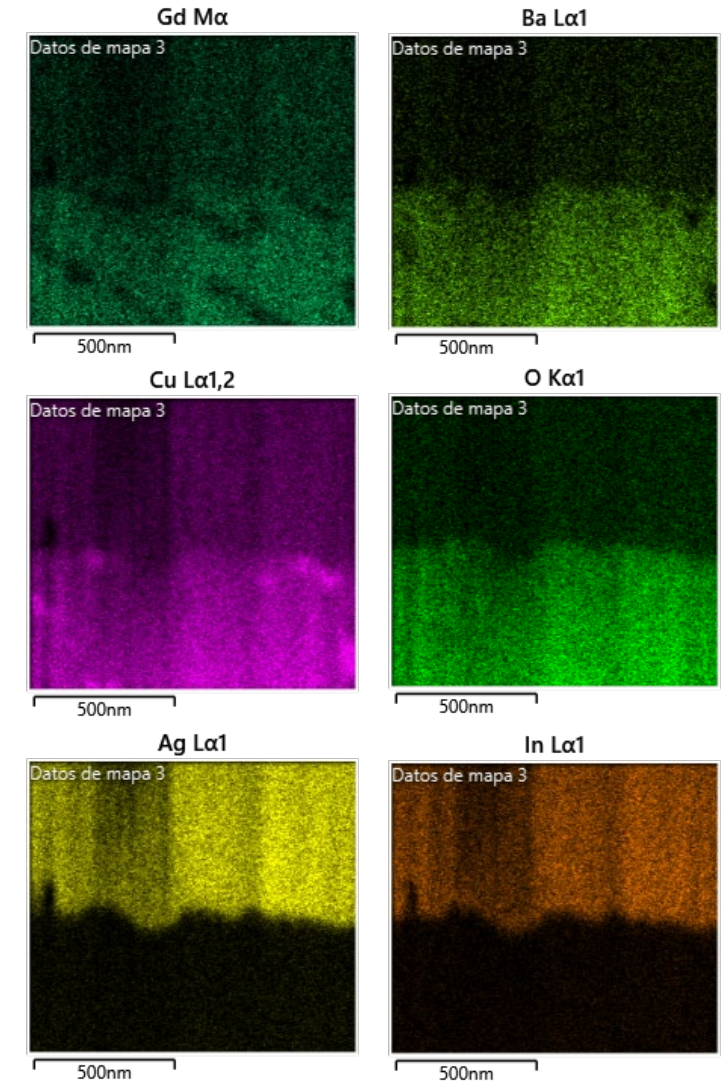
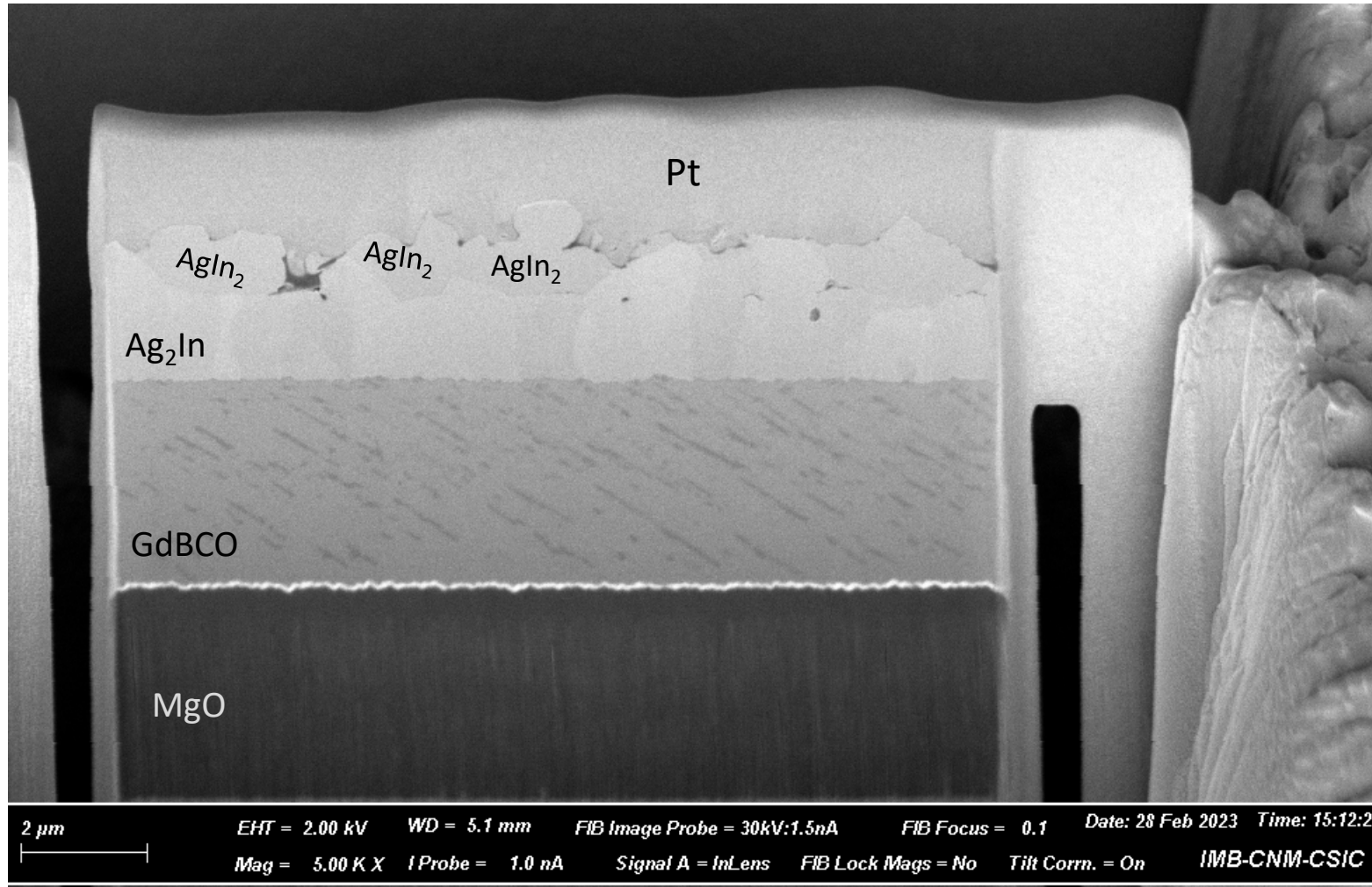
$\tau = 14 \text{ hours}$



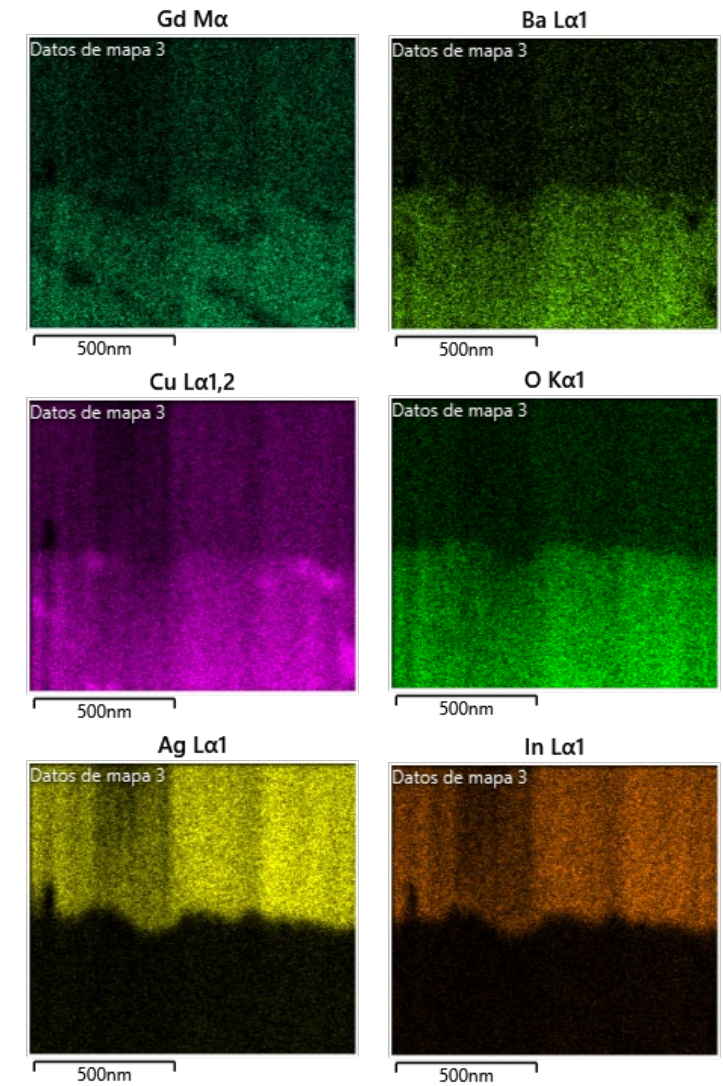
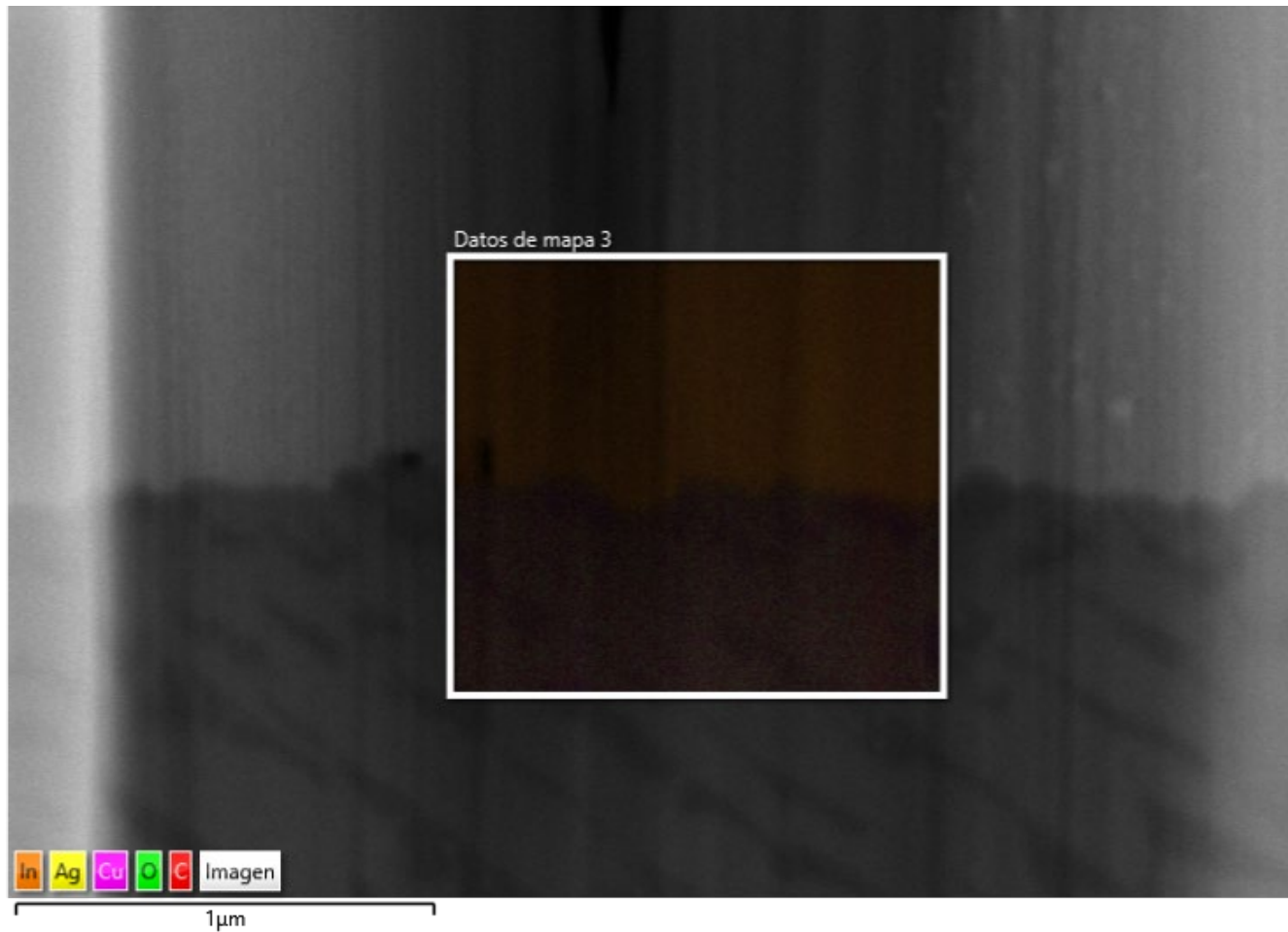
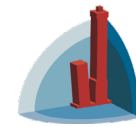
Schematic model of the sequence of reaction and compound formation in Ag/In bilayer polycrystalline film (In < Ag): (a) as deposited; (b) AgIn₂ layer due to ambient diffusion; (c) growth of Ag₂In layer near the interface and at the silver grain boundaries at ambient temperature with aging or at higher temperature; (d) further growth of Ag₂In throughout the specimen and on the silver underlayer.

Fig. 3. Variation in diffusion coefficient $\ln D(t)$, as obtained from the plots presented in Fig. 2, with reciprocal absolute temperature $1/T$.

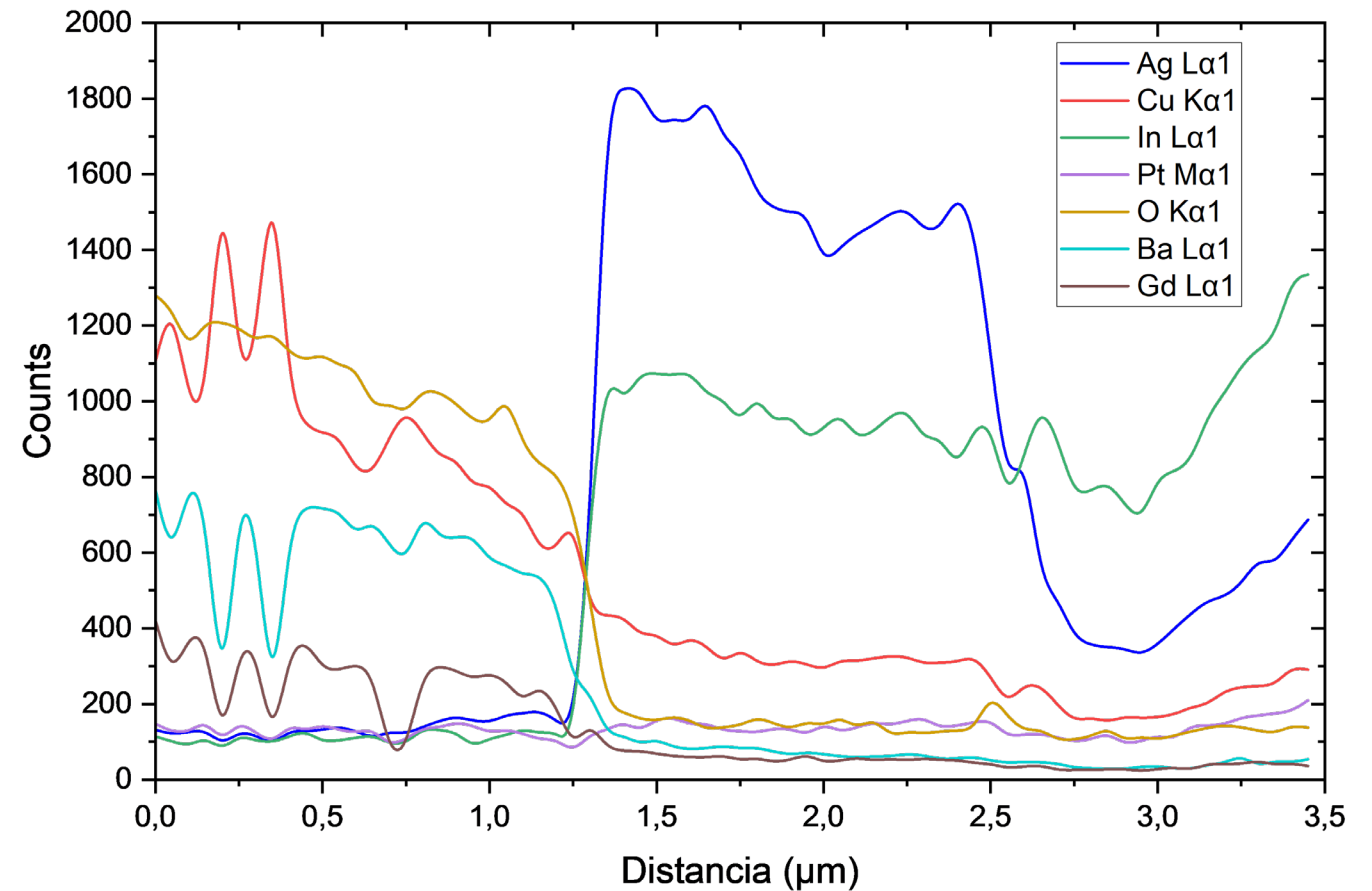
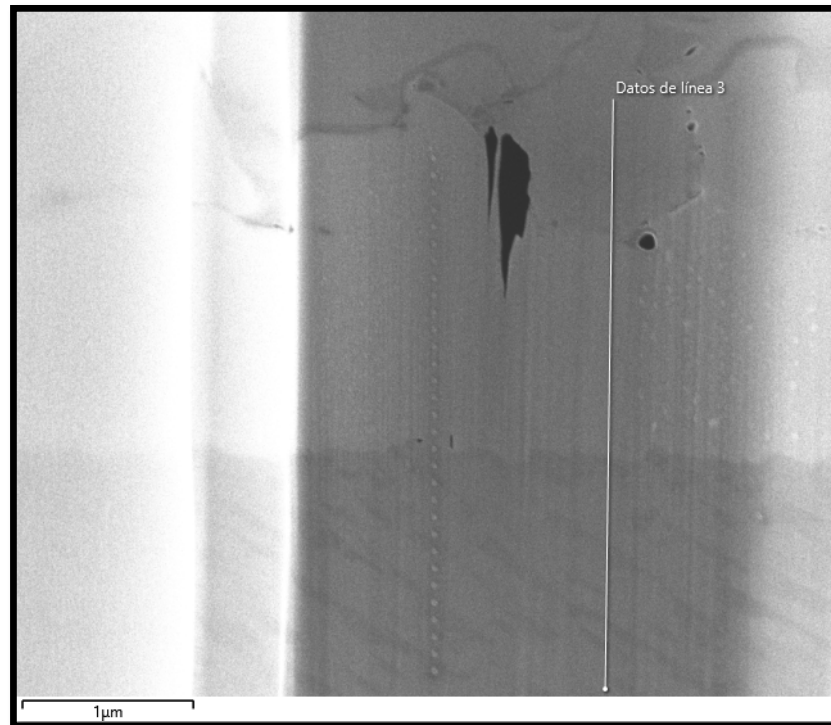
SEM-FIB image of the IMC-CFD In cross-section



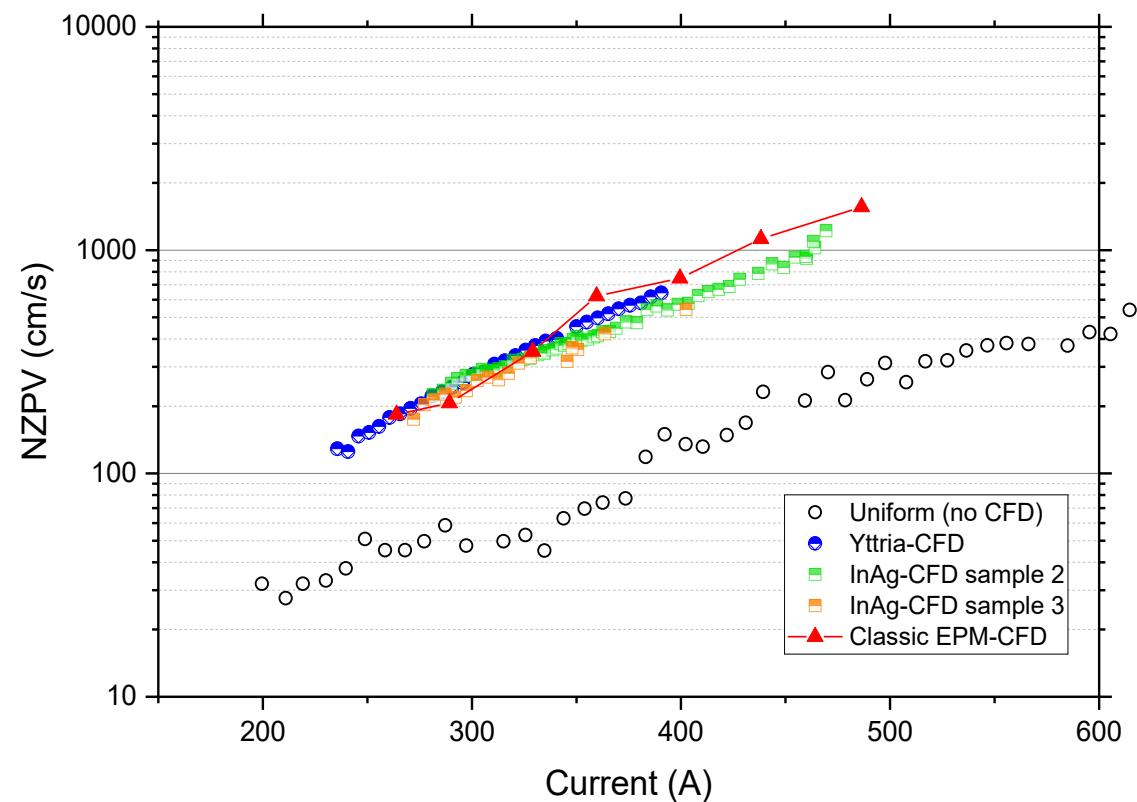
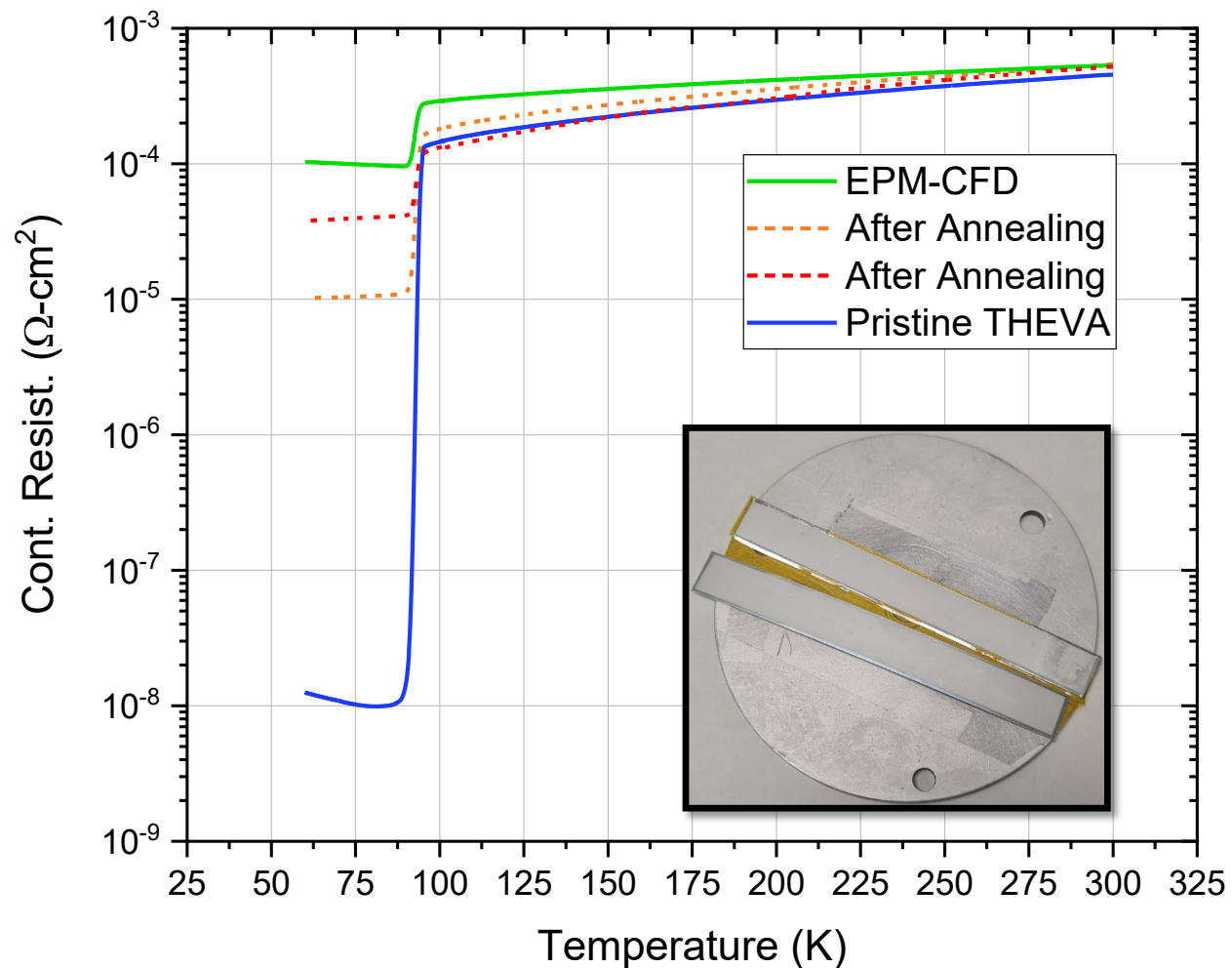
3rd Proposal: Map-EDX Analysis of Indium IMC-CFD



✓ Minimal diffusion of the In into the GdBCO layer (< 5 nm).

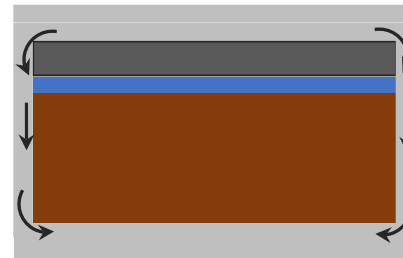
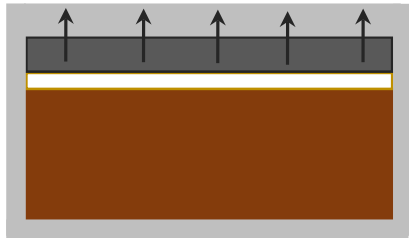


3rd Proposal: Interfacial resistance & NZPV tests



4th Proposal: b-CFD via silver sulfidation

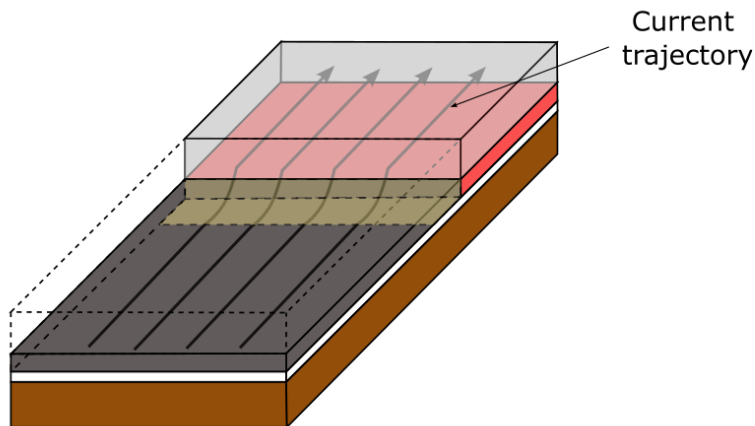
Tape cross section



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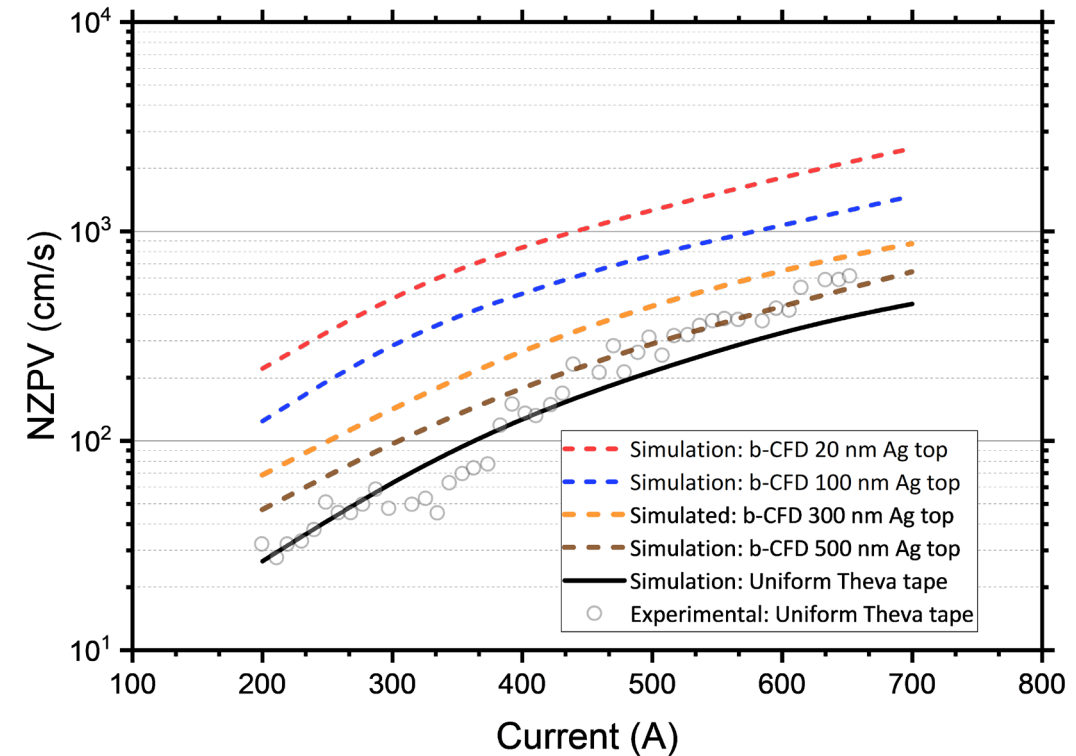


COMSOL



- Hastelloy Substrate
- REBCO film
- Buffer layer
- Silver stabilizer
- Normal zone
- Joule heating concentration
- High interfacial resistance layer

Lacroix et al., SUST 27 035003 (2014)
Lacroix et al., SUST 27 055013 (2014)
Lacroix et al., SUST 30 064004 (2017)



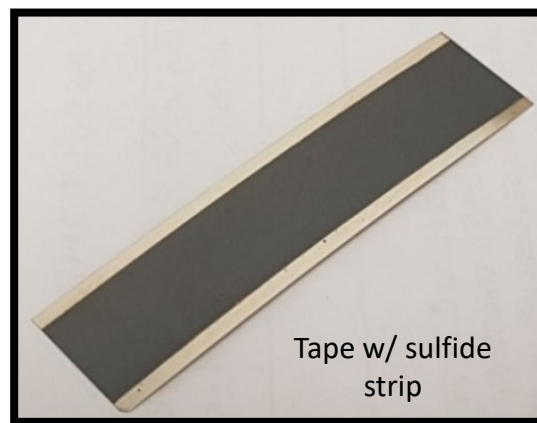
Lacroix et al., SUST 35 055009 (2022)
Barusco et al. To be published

4th Proposal: The b-CFD architecture with sulfidation

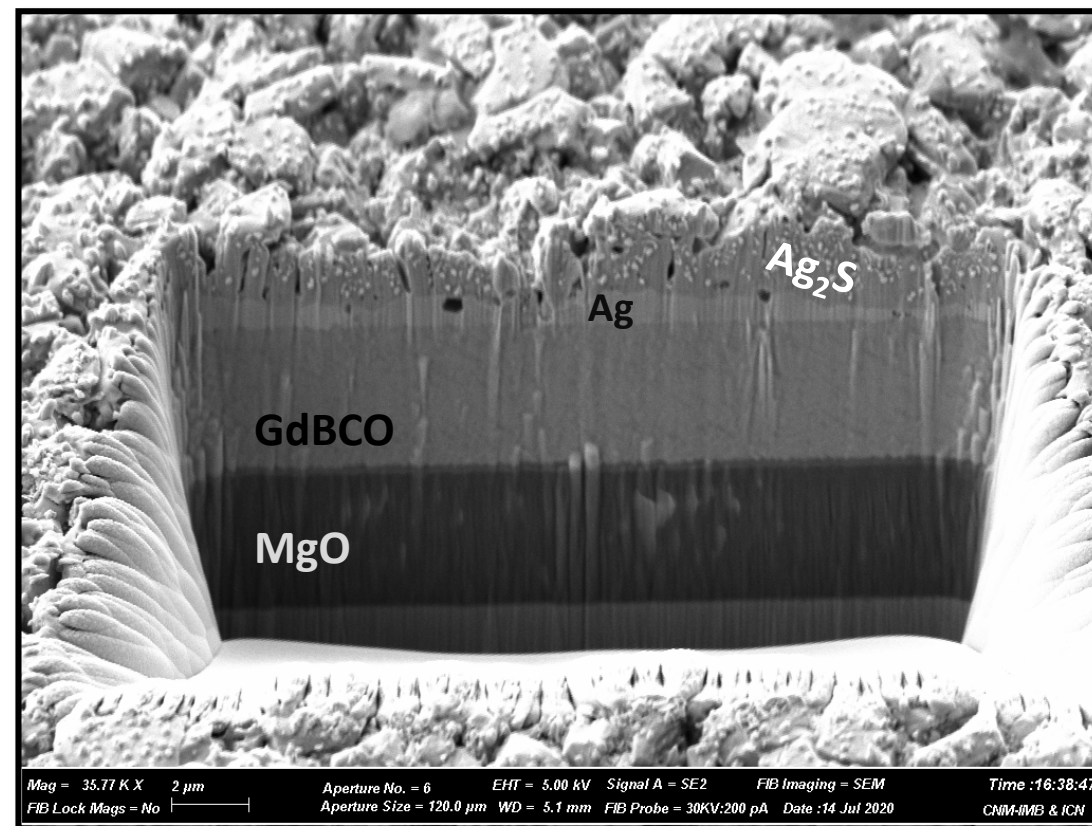
Partial Sulfidation of the Ag shunt:



- GdBa₂Cu₃O₇
- MgO
- Hastelloy
- Silver (Ag)
- Silver sulfide (Ag₂S)



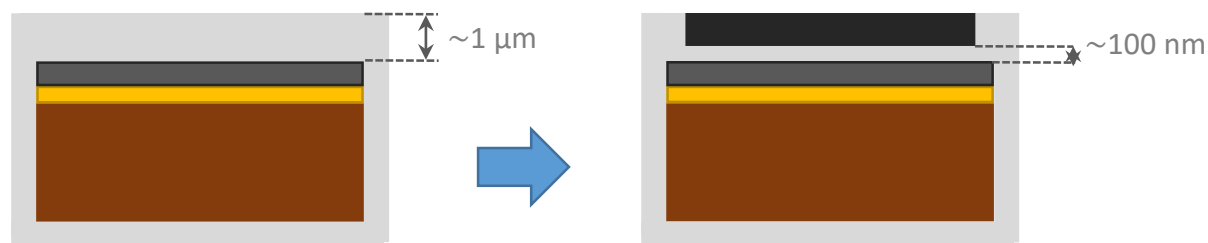
The sulfidation process can be controlled to avoid damaging the HTS



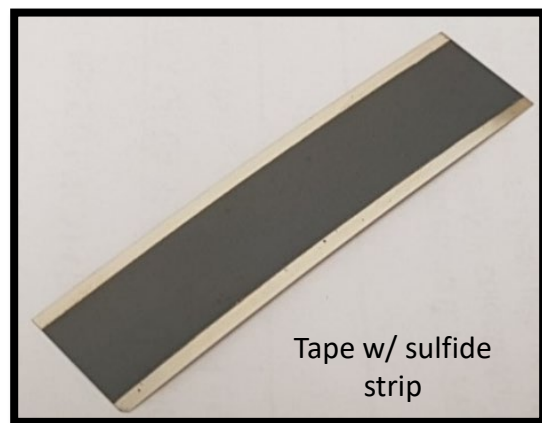
Barusco et al., in publishing

4th Proposal: The b-CFD architecture with sulfidation

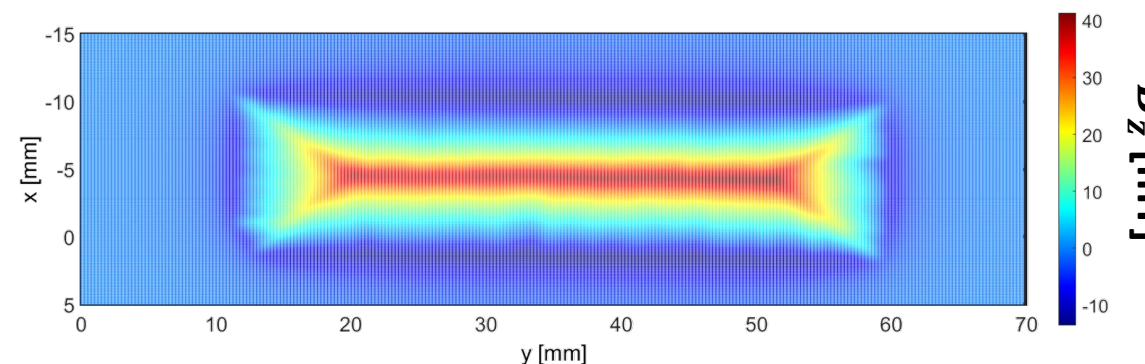
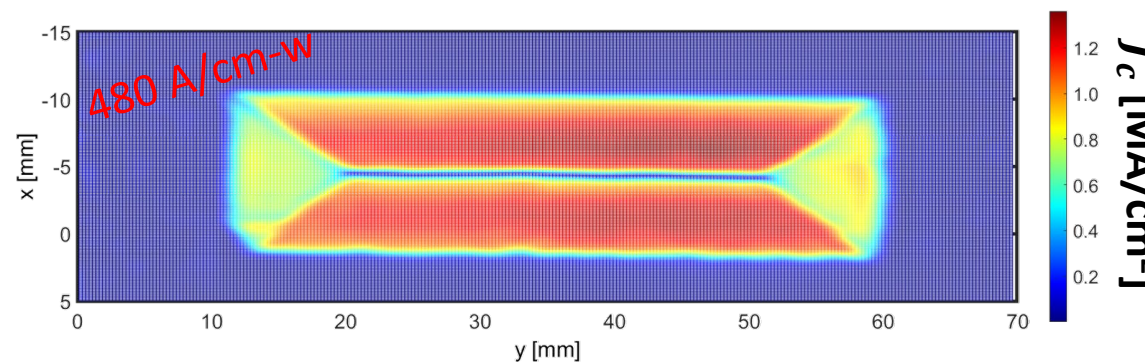
Partial Sulfidation of the Ag shunt:



- GdBa₂Cu₃O₇
- MgO
- Hastelloy
- Silver (Ag)
- Silver sulfide (Ag₂S)



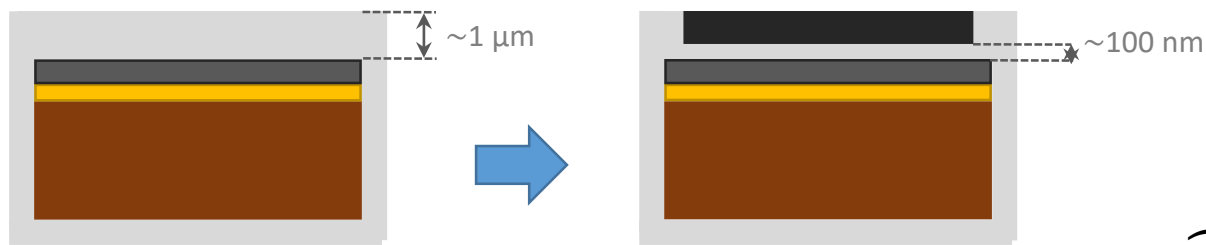
The sulfidation process can be controlled to avoid damaging the HTS



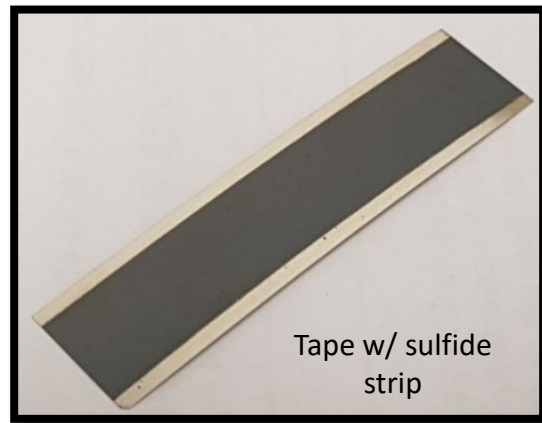
Barusco et al., in publishing

4th Proposal: The b-CFD architecture with sulfidation

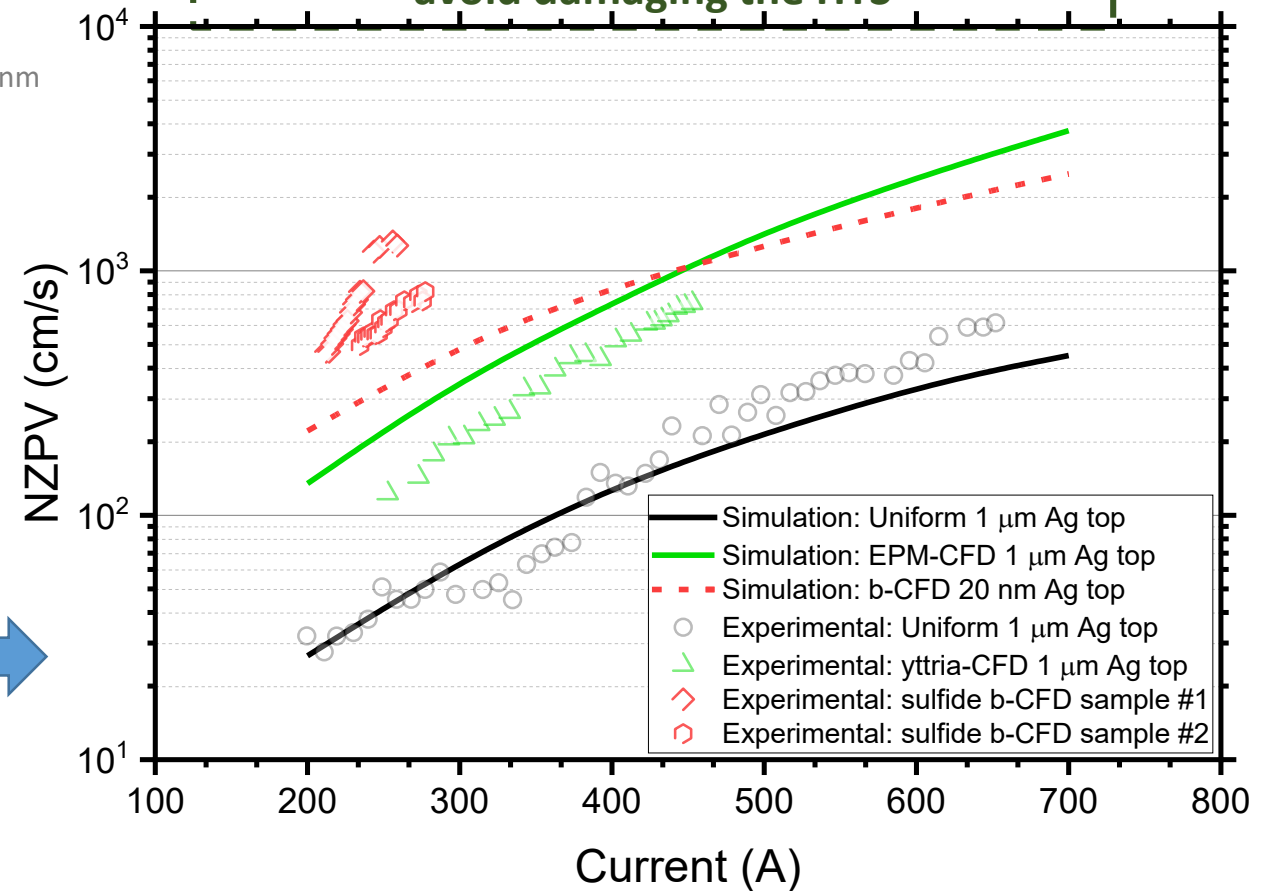
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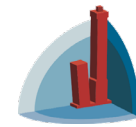


The sulfidation process can be controlled to avoid damaging the HTS



Barusco et al., in publishing

Conclusions

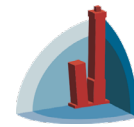


Technique	Pros	Cons
Local Annealing	<ul style="list-style-type: none"> Extremely high NZPV Ultra simple technique/ no extra machinery required 	<ul style="list-style-type: none"> Two Extra steps: Pre-oxygenation + Local Annealing MUST customize the Tape's length
Classic CFD (CFD)	<ul style="list-style-type: none"> 5-10x increase in the NZPV No need to customize the length Relatively simple implementation 	<ul style="list-style-type: none"> Two extra steps: Ag etch & Ag re-sputtering Waste of expensive silver material
CFD-Yttria	<ul style="list-style-type: none"> 5-8x increase in the NZPV Cheap CSD process 	<ul style="list-style-type: none"> Two extra steps: Pre-oxygenation & Yttria-CSD MUST Avoid silver diffusion during annealing
CFD-Indium	<ul style="list-style-type: none"> 5-8x increase in the NZPV Compatible with the standard silver-coated CCs 	<ul style="list-style-type: none"> Two extra steps: In deposition and annealing Indium is cheaper than Ag but still pricy
bCFD-Sulfide	<ul style="list-style-type: none"> Same performance as the bCFD Cheap Sulfidation process Compatible with the standard silver-coated CC 	<ul style="list-style-type: none"> Not yet compatible with a Cu shunt Requires controlling the gas reaction in an R2R process

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- CNRS / Institut Neel (NEEL)

Industry

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